MPQ4371



36V, 6A to 11A, Low-EMI, Synchronous Step-Down Converter with ZDP™, AEC-Q100 Qualified

DESCRIPTION

The MPQ4371 family of buck converters are configurable-frequency (200kHz to 2.5MHz), synchronous, step-down switching regulators with integrated low on-resistance HS-FETs and LS-FETs. The family covers a 6A to 11A output current (I_{OUT}) range and employs zero-delay PWM (ZDPTM) control, an MPS-exclusive technology that delivers fast transient response while reducing external capacitor count.

The wide 3.3V to 36V input voltage (V_{IN}) range accommodates a variety of step-down applications in automotive input environment. A 1.8 μ A shutdown mode quiescent current allows use in battery-powered applications. High power conversion efficiency across the wide load range is achieved by scaling down the switching frequency (f_{SW}) under light loads to reduce the switching and gate driving losses.

An open-drain power good signal indicates when the output is within 94% to 106% of its nominal voltage. Frequency foldback prevents inductor current runaway during start-up. Thermal shutdown provides reliable, fault-tolerant operation. A high duty cycle and low-dropout mode support automotive cold-crank conditions.

The MPQ4371 is available in QFN-23 (4mmx5mm) or TQFN-23 (4mmx5mm) packages with wettable flanks. It is available in AEC-Q100 Grade 1.

FEATURES

- Designed for Automotive Transients
 - 3.3V to 36V Input Voltage (V_{IN}) Range
 - Load Dump Up to 42V
 - Low-Dropout (LDO) Mode
 - Available in AEC-Q100 Grade 1
- Highly Scalable Family
 - 6A to 11A Output Current (I_{OUT})
 Versions in Pin-Compatible Family
- Multi-Phase Capabilities Up to 8 Phases
 Designed for High-Performance and
 - Reduced Component Overhead
 O ZDP™ Control for Fast Transient Response and Fewer Capacitors

FEATURES (continued)

- ±1% Output Accuracy
- \circ ~ Fixed or Adjustable V_{OUT} Options ~
- Fixed Output ⁽¹⁾: 1V, 1.2V, 1.8V, 2.5V, 3.3V, 3.8V, or 5V
- Adjustable Vout Up to 12V
- Internal Soft Start
- o Output Discharge from SW
- o 30ns Minimum On Time
- High Efficiency for Increased Battery Life and Improved Thermals
 - 1.8µA Shutdown Current, 3.5µA Standby Current
 - AAM Mode Increases Efficiency under Light Loads
 - Integrated Low Resistance High-Side and Low-Side MOSFETs (22mΩ/11mΩ)
- Optimized for Low EMC/EMI
 - 200kHz to 2.5MHz Configurable f_{SW}
 - Symmetric VIN Pinout Placement
 - Low Noise at High Frequency Band by Quiet-FET™ Switching Technology
 - FSS Modulation
 - Synchronization to an External Clock
 - CISPR25 Class 5 Compliant
 - Mesh-Connect[™] Package
 - Available in QFN-23 (4mmx5mm) or TQFN-23 (4mmx5mm) Packages with Wettable Flanks
- Functional Safety System Design Capability

 MPSafe[™]-Compatible: Functional
 - Safety Supporting Document Available



APPLICATIONS

- Automotive Infotainment
- Telematics
- Advanced Driver-Assistance Systems (ADAS)
- Industrial Power Systems

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Note:

 See the Ordering Information section on page 3 for the exact availability of each fixed output version. Additional output voltages may be available. Contact MPS for details.



TYPICAL APPLICATION

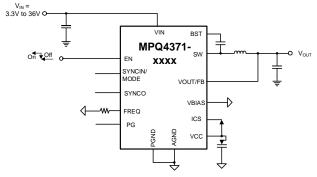
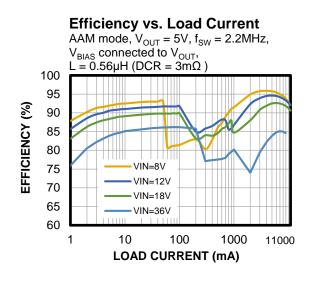


Figure 1: Fixed Output Version



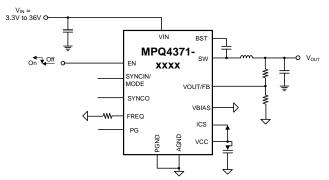
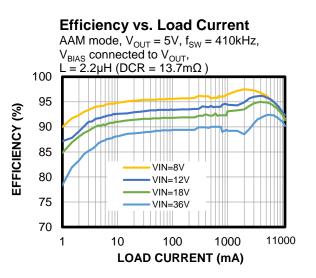


Figure 2: Adjustable Output Version





ORDERING INFORMATION

Part Number ^{(2)(3)*}	Package	Top Marking	MSL Rating**
MPQ4371GVE-xxxx-AEC1***	QFN-23 (4mmx5mm)	See Below	1
MPQ4371GVTE-xxxx-AEC1***	TQFN-23 (4mmx5mm)	See Below	1

* For Tape & Reel, add suffix -Z (e.g. MPQ4371GVE-xxxx-AEC1-Z).

** Moisture Sensitivity Level Rating

*** Wettable Flank

Notes:

3)

2) Contact MPS for details regarding fixed-output versions.

The detailed information of part number can be marked as MPQ4371-WXYZ. Table 1 shows the meaning of 4-digit code.

Digit Code	Naming Rule
	1: 11A
W/ Defines the new included surrout	0: 10A
W: Defines the nominal load current	8: 8A
	6: 6A
	0: Adjustable output
	1: Fixed 1V output
	A: Fixed 1.2V output
V: Defines the output veltage	B: Fixed 1.8V output
X: Defines the output voltage	2: Fixed 2.5V output
	3: Fixed 3.3V output
	4: Fixed 3.8V output
	5: Fixed 5V output
Y: Defines the frequency spread spectrum	0: With FSS
(FSS) configuration	A: Without FSS
7: Defines the multi phase espability	0: Single-phase
Z: Defines the multi-phase capability	1: Multi-phase

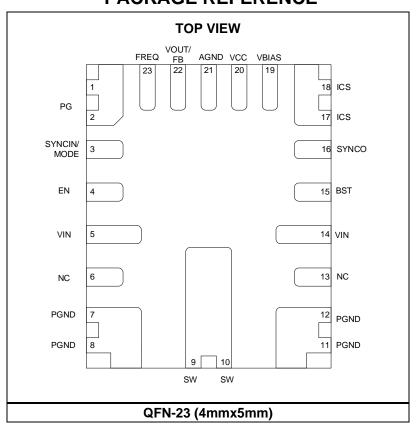
Table 1: Part Number Digit Code Naming Rules

TOP MARKING

MPSYWW MP4371 LLLLLL E

MPS: MPS prefix Y: Year code WW: Week code MP4371: Part number LLLLLL: Lot number E: Wettable flank





PACKAGE REFERENCE



PIN FUNCTIONS

Pin #	Name	Description
1, 2	PG	Power good (PG) output and secondary phase selection. The output of the PG pin is an open drain. For single-phase applications, PG must be connected to a power source by a pull-up resistor if the PG function is used. PG goes high if the output voltage (V _{OUT}) is within 94% to 106% of the nominal voltage; PG goes low if V _{OUT} exceeds 107% or falls below 93% of the nominal voltage. In single-phase applications, float PG when it is not used. For multi-phase applications, if the device is in primary mode, the PG pin's function is the same as it would be for a single-phase application. If the device is in secondary mode, connect a resistor to ground to set the phase shift. Then power good indication is disabled and does not pull high. The PG pin cannot be left floating for secondary devices. See the
3	SYNCIN/ MODE	Power Good (PG) Indication or Phase Shift Setting section on page 70 for more information. External sync input and primary mode selection. Apply a clock signal to this pin to synchronize the internal oscillator frequency to the external clock. If the device is set as a primary device, use an external clock or pull this pin high to enter forced continuous conduction mode (FCCM). Pull this pin low to enable discontinuous conduction mode (DCM) and pulse-skipping at light loads. The pin has a weak internal pull-down resistor, so this pin can be floating to set advanced asynchronous modulation (AAM) mode. When the part is set as a secondary device, connect this pin to the primary device's SYNCO pin.
4	EN	Enable. Pulling this pin below the specified threshold (0.85V) shuts the chip down. Pulling EN above the specified threshold (1V) enables the chip. EN can be directly connected to VIN. Do not float this pin.
5, 14	VIN	Input supply. VIN supplies power to all the internal control circuitry and the power switch connected to SW. A proper decoupling capacitance must be connected between VIN and PGND at each side of the IC to minimize switching spikes.
6, 13	NC	No connection. The NC pin does not have an internal connection to the die. It can be left floating.
7, 8, 11, 12	PGND	Power ground. Connect the PGND pin to a large GND plane to ensure excellent heat dissipation.
9, 10	SW	Switch node. The SW pin is connected to the high-side MOSFET's source and the low- side MOSFET's drain. Connect the power inductor to this pin with a wide trace and limit its area to avoid EMI radiation.
15	BST	Bootstrap. The BST pin is the positive power supply for the high-side MOSFET driver connected to SW. Connect a bypass capacitor between BST and SW.
16	SYNCO	Sync output and mode select for secondary. When SYNCO is at high impedance, the device operates in primary operation mode, this pin outputs a clock signal in phase with the internal oscillator signal or external clock at the SYNCIN/MODE pin. In single-phase operation, this pin must be floating. In multi-phase applications, if this pin is tied to a low-impedance ground, voltage source, or clock, the device operates as a secondary device. When working as a secondary device, this pin selects the light-load operating mode (high for FCCM; low for AAM mode). In multi-phase applications, connect the SYNCO pin of all secondary devices together with the primary device's SYNC/MODE pin.
17, 18	ICS	Current-sharing pin. In a single-phase applications, connect ICS to the VCC pin. In a multiphase application, connect the ICS pins from all the parts together in order to improve the current sharing between the different phases.



PIN FUNCTIONS (continued)

Pin #	Name	Description
		Internal LDO supply. VBIAS is the power supply for the VCC regulator.
19	VBIAS	The VCC regulator uses VBIAS as a power supply if the BIAS pin's voltage (V_{BIAS}) is between 4.5V and 5.5V. This pin can be connected directly to the output voltage when V_{OUT} is between 4.6V to 5.5V to improve the converter's efficiency, especially at high frequencies. Alternatively, connect this pin to another 5V rail if it is available in the system, and the current draw is <30mA. Add one decoupling capacitor between the VBIAS pin and GND if this function is used.
		When there is no suitable power source for VBIAS, or the function is not used, connect this pin to the output voltage or GND.
		If $V_{OUT} > 5.5V$, avoid connecting the VBIAS pin to the output. Avoid providing an external VBIAS voltage before VIN. Do not float this pin.
20	VCC	Internal LDO output. VCC supplies 5V of power to the internal control circuit and gate drivers. A decoupling capacitor must be connected from VCC to AGND, and placed close to this pin.
21	AGND	Analog ground. Connect the AGND pin to the DC/DC GND and close to the VCC capacitor.
		V _{OUT} regulation input / feedback divider. For the fixed-output version, connect this pin to the output voltage directly to regulate V _{OUT} .
22	VOUT/FB	For the adjustable-output version, set Vout by connecting FB to the center point between the external resistor divider from the output and AGND. The feedback voltage is 0.6V. Place the resistor divider as close to FB as possible. Avoid placing many vias on the FB traces.
23	FREQ	Switching frequency configurations. Connect a resistor from the FREQ pin to ground to set the switching frequency (fsw).



ABSOLUTE MAXIMUM RATINGS (4)

VIN, EN	0.3V to +42V
SW0.3V	to $V_{IN(MAX)}$ + 0.3V
BST	V _{SW} + 5.5V
VBIAS	0.3V to +6V
All other pins	0.3V to +6V
Continuous power dissipation	$(T_A = 25^{\circ}C)^{(5)(9)}$
QFN-23 (4mmx5mm)	5.48 W
Junction temperature (T _J)	150°C
Lead temperature	260°C
Storage temperature	-65°C to +150°C

ESD Ratings

Human body model (HB	5M)	Class 2 ⁽⁶⁾
Charged-device model ((CDM)	Class C2b ⁽⁷⁾

Recommended Operating Conditions

Input voltage (V _{IN})	3.3V to 36V
V _{BIAS}	
Output voltage (V _{OUT})	
Operating junction temp (T _J)	40°C to +150°C

Thermal Resistance θ_{JA} θ_{JC}

QFN-23 (4mmx5mm)			
JESD51-7	41.2	3.9	°C/W ⁽⁸⁾
EVQ4371-V-00A	22.8		°C/W ⁽⁹⁾
		$oldsymbol{\psi}_{JT}$	
JESD51-7		. 0.5	°C/W ⁽⁸⁾
EVQ4371-V-00A		.1.14	°C/W ⁽⁹⁾
TQFN-23 (4mmx5mm)			
JESD51-7	41.2	3.9	°C/W ⁽⁸⁾
		$oldsymbol{\psi}_{JT}$	
JESD51-7		. 0.4	°C/W ⁽⁸⁾

Notes:

- 4) Exceeding these ratings may damage the device.
- 5) The maximum allowable power dissipation is a function of the maximum junction temperature, T_J (MAX), the junction-toambient thermal resistance, θ_{JA} , and the ambient temperature, T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX) - T_A) / θ_{JA} . Exceeding the maximum allowable power dissipation can cause excessive die temperature, and the regulator may go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 6) Per AECQ100-002.
- 7) Per AECQ100-011.
- 8) Measured on a JESD51-7, 4-layer PCB. The values given in this table are only valid for comparison with other packages and cannot be used for design purposes. These values were calculated in accordance with JESD51-7, and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application. The value of θ_{Jc} shows the thermal resistance from junction-to-case bottom. The value of Ψ_{JT} shows the characterization parameter from junction-to-case top.
- 9) Measured on an MPS standard EVB: 8.3cmx8.3cm, 2oz. copper thickness, 4-layer PCB. The value of $\Psi_{\rm JT}$ shows the characterization parameter from junction-to-case top.



ELECTRICAL CHARACTERISTICS

$V_{IN} = 12V$, $V_{EN} = 2V$, $T_J = -40^{\circ}C$ to +150°C, typical values are at $T_J = 25^{\circ}C$, unless otherwise noted..

Parameter	Symbol	Condition	Min	Тур	Max	Units
Input Supply		· · ·				
Input voltage (V _{IN}) under- voltage lockout (UVLO) rising threshold	VIN _{UV_RISING}		3.6	3.8	4.1	V
V _{IN} UVLO falling threshold	$VIN_{UV_FALLING}$		2.7	2.9	3.1	V
VIN UVLO hysteresis	VIN _{UV_HYS}			0.9		V
VIN quiescent current (10)	lα	$\label{eq:FB} \begin{array}{l} FB = 0.63 V, \mbox{ no load}, \\ SYNCIN/MODE = GND \\ (AAM mode), \mbox{ non-switching}, \\ T_{J} = -40 \mbox{ to } +85^\circ C \end{array}$		3.5	8.6	μA
vin quescent current a	ių.	$\label{eq:synchronomy} \begin{array}{l} FB = 0.63V, \mbox{ no load}, \\ SYNCIN/MODE = GND \\ (AAM mode), \mbox{ non-switching}, \\ T_J = -40 \mbox{ to } +125^\circC \end{array}$			15	μA
VIN quiescent current		SYNCIN/MODE = GND (AAM mode), switching, $V_{BIAS} = 5V$, no load, $T_J = -40$ to +85°C		4.5	9	μA
(switching) ⁽¹⁰⁾	IQ_SLEEP	SYNCIN/MODE = GND (AAM mode), switching, $V_{BIAS} = 5V$, no load, $T_J = -40$ to +125°C			16.5	μA
VIN active current (non- switching)	IQ_ACTIVE	FB = 0.63V, no load, SYNCIN/MODE = VCC (CCM), non-switching		1300	2300	μA
VIN shutdown current	Lever.	$EN = 0V$, $T_J = -40^{\circ}C$ to $+85^{\circ}C$		1.8	4	μA
	Ishdn	EN = 0V			22.5	μA
V _{IN} over-voltage protection (OVP) threshold	VINOVP_RISING		36	38	40	V
VIN OVP hysteresis	VINOVP_HYS			1		V
VCC and VBIAS				-		
VCC voltage	Vcc	$I_{VCC} = 0mA$, VCC from VIN	4.8	5.0	5.2	V
VOO VORage	VCC	$I_{VCC} = 30 \text{mA}, V_{\text{BIAS}} = 5 \text{V}$		3.8 4.1 2.9 3.1 0.9 3.1 3.5 8.6 3.5 8.6 4.5 9 4.5 9 1100 16.5 11300 2300 1.8 4 22.5 38 38 40 1 1		V
VCC regulation		Ivcc = 30mA				%
VCC current limit	ILIMIT_VCC	$V_{CC} = 4V$	89			mA
		Vcc = 0V	40	70	120	mA
VBIAS take-over rising threshold	VBIAS-RISING			4.5		V
VBIAS take-over hysteresis				200		mV
Soft Start						
Soft-start time	t _{SS}	EN high to PG high	4	5	6	ms



ELECTRICAL CHARACTERISTICS (continued)

$V_{IN} = 12V$, $V_{EN} = 2V$, $T_J = -40^{\circ}C$ to +150°C, typical values are at $T_J = 25^{\circ}C$, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
EN Function		•		•		
EN rising threshold	VEN_RISING		0.8	1	1.2	V
EN falling threshold	Ven_falling		0.65	0.85	1.05	V
EN hysteresis voltage	V _{EN_HYS}			150		mV
Output and Regulation		·				
FB voltage (adjustable output version)	Vfb		594	600	606	mV
V _{OUT} regulation voltage (fixed output version)	Vout_reg	V _{IN} = 3.3V to 36V	-1		+1	%
FB leakage in fixed output version	Ivout	$V_{OUT} = V_{VOUT_REG}$		2.3		μA
FB leakage in adjustable output version		FB = 0.63V		1	100	nA
Vout Discharge from SW	Idischarge	EN = 0V, $V_{OUT} = 0.3V,$ $V_{IN} = 3.3 \text{ to } 36V$	2			mA
Switches and Frequency						
Minimum on time ⁽¹⁰⁾	ton_min		12	30	35	ns
Minimum off time ⁽¹⁰⁾	t _{OFF_MIN}			100	125	ns
Minimum off time in low-dropout mode ⁽¹⁰⁾				50	60	ns
Switch leakage current	I _{SW_LKG}			0.01	9	μA
High-side MOSFET (HS-FET) on resistance	Ron_Hs	V _{BST} -V _{SW} = 5V		22	42	mΩ
Low-side MOSFET (LS-FET) on resistance	Ron_ls	Vcc = 5V		11	22	mΩ
		$R_{FREQ} = 88.7 k\Omega$	370	410	450	kHz
Switching frequency	fsw	$R_{FREQ} = 33k\Omega$	900	1000	1100	kHz
		$R_{FREQ} = 15k\Omega$	1980	2200	2420	kHz
SYNCIN and SYNCO				-		
SYNCIN voltage rising threshold	VSYNC_RISING				1.4	V
SYNCIN voltage falling threshold	VSYNC_FALLING		0.4			V
SYNCIN timeout	t MODE	SYNCIN/MODE low to DCM	30		65	μs
SYNCIN clock range	fsync	% of free-running frequency (fsw)	90		110	%
SYNCO high voltage	V _{SYNCO_} HIGH	Isynco = -1mA	3.3	4.5		V
SYNCO low voltage	VSYNCO_LOW	I _{SYNCO} = 1mA			0.4	V
BST						
BST-SW refresh rising threshold	VUVBST-SW-RISING			2.5		V
BST-SW refresh falling threshold	VUVBST-SW-FALLING			2.3		V
BST-SW refresh hysteresis	VUVBST-SW_HYS		0.19			V



ELECTRICAL CHARACTERISTICS (continued)

$V_{IN} = 12V$, $V_{EN} = 2V$, $T_J = -40^{\circ}C$ to +150°C, typical values are at $T_J = 25^{\circ}C$, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
ICS	·		•	•		•
Current-sharing gain	Gcs			30		mV/A
PG Function	•	·	•	•		
DC rising threshold	N/	V _{OUT} rising	91%	94%	97%	
PG rising threshold	Vpgvth_rising	Vout falling	103%	106%	109%	1
DO falling threads and		Vout falling	90%	93%	96%	Vout
PG falling threshold	Vpgvth_falling	Vout rising	104%	107%	110%	V001
PG trip threshold hysteresis	Vpgvth_hys			1		
PG output voltage low	Vpg_low	ISINK = 1mA		10	100	mV
PG rising deglitch	tpg_r_delay			120		μs
PG falling deglitch	tpg_f_delay			100		μs
Protections						
		Duty cycle = 30%, for MPQ4371-1XYZ	16.6	19	22	A
HS current limit (11)	h	Duty cycle = 30%, for MPQ4371-0XYZ	371-0XYZ 15.2 1	17.2	19	
	LIMIT_HS	Duty cycle = 30%, for MPQ4371-8XYZ	12.6	13.8	15	
		Duty cycle = 30%, for MPQ4371-6XYZ	8.6	10.3	12	
		Duty cycle = 30%, for MPQ4371-1XYZ	11.2	13.2		
LS valley current		Duty cycle = 30%, for MPQ4371-0XYZ	10.2	13	15.2	A
limit ⁽¹¹⁾	ILIMIT_LS	Duty cycle = 30%, for MPQ4371-8XYZ	8.2	9.6		A
		Duty cycle = 30%, for MPQ4371-6XYZ	6.2	7.2		
Zero-current detection (ZCD) current	Izcd	AAM mode	0	100	300	mA
LS reverse current limit	ILIMIT_REVERSE	FCCM	-5.2	-4	-2.8	A
Thermal shutdown	T _{SD}		150	180		°C
Thermal shutdown hysteresis ⁽¹⁰⁾	T _{SD_HYS}			30		°C

Notes:

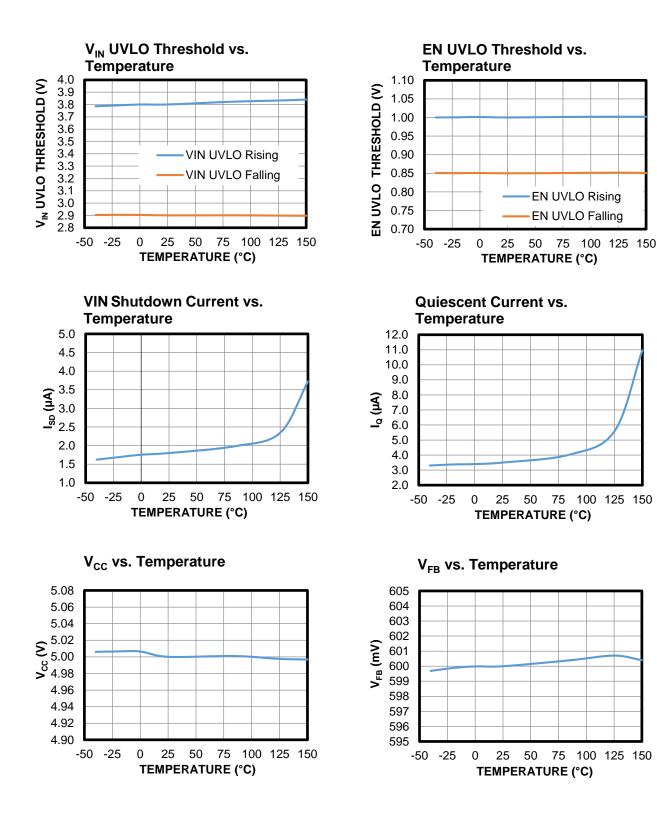
10) Derived from bench characterization, not tested in production.

11) Cannot test in production for the MPQ4371-1XYZ/8XYZ/6XYZ. Guaranteed by design and bench test characterization.



TYPICAL CHARACTERISTICS

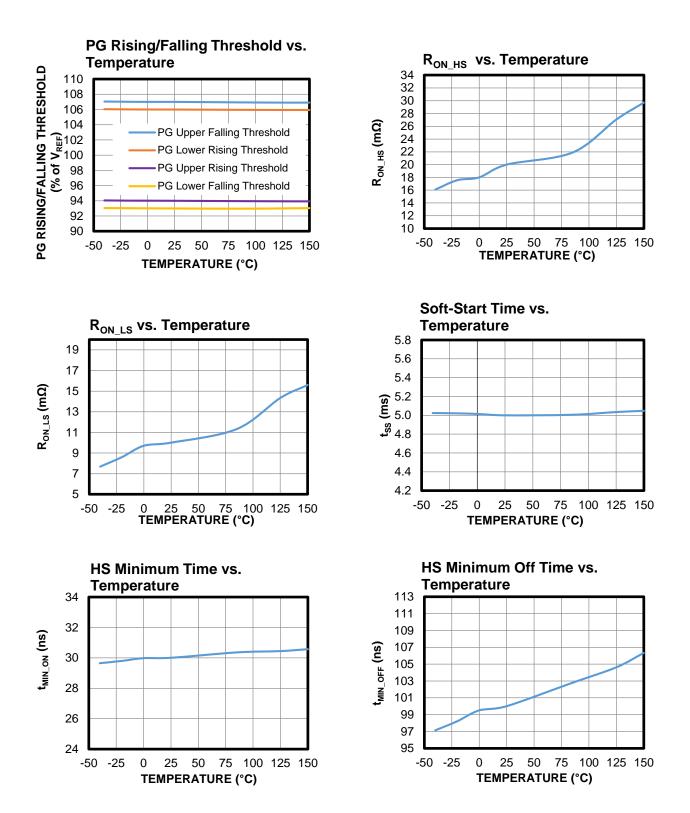
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TYPICAL CHARACTERISTICS (continued)

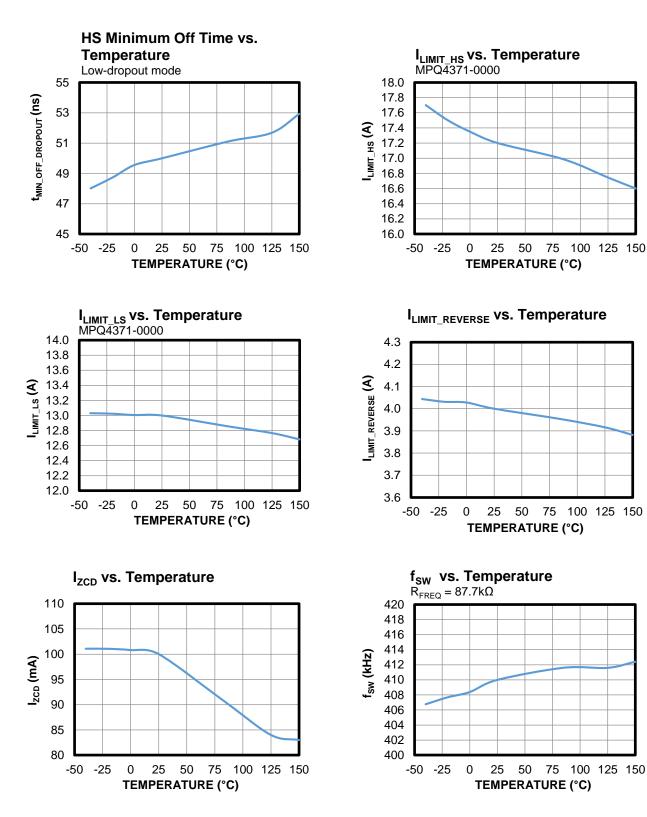
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TYPICAL CHARACTERISTICS (continued)

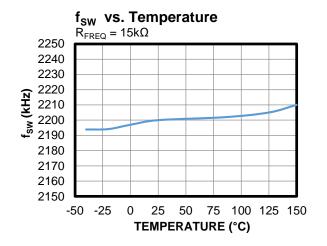
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TYPICAL CHARACTERISTICS (continued)

 V_{IN} = 12V, V_{OUT} = 5V, T_{J} = -40°C to +150°C, unless otherwise noted.





VIN=8V VIN=12V

VIN=18V

VIN=36V

VIN=8V

VIN=12V VIN=18V

VIN=36V

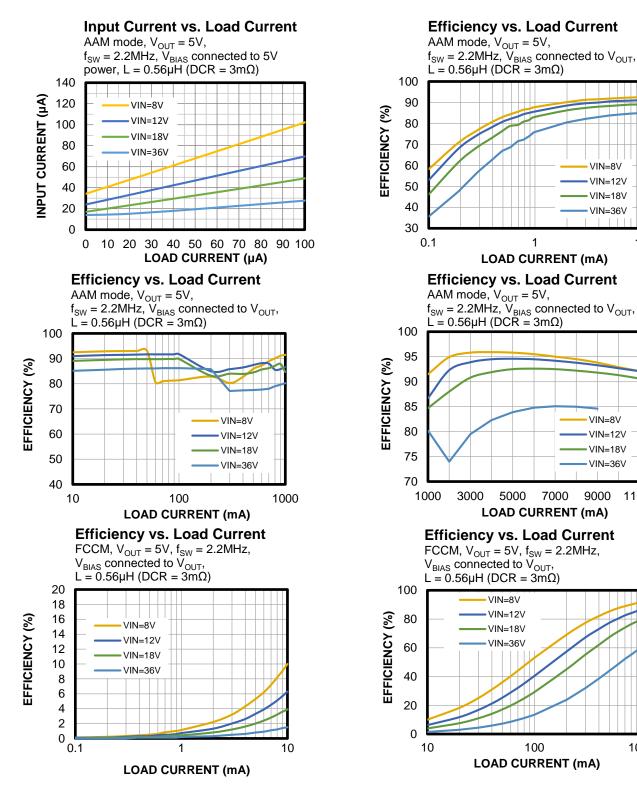
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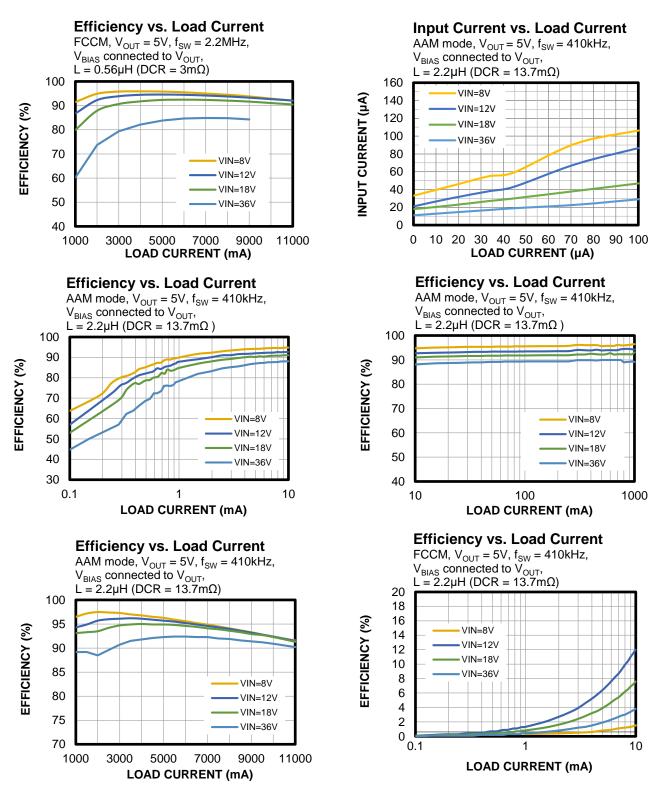
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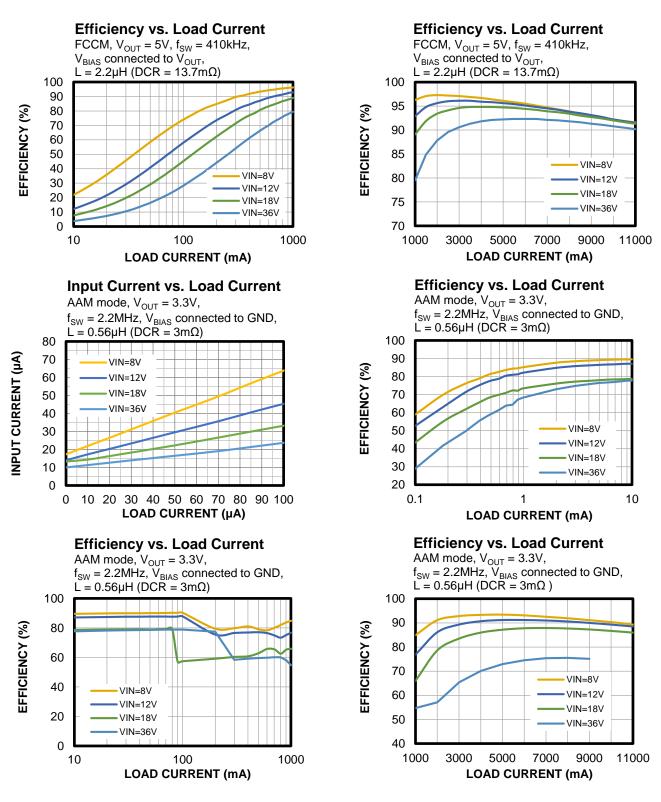
TYPICAL PERFORMANCE CHARACTERISTICS



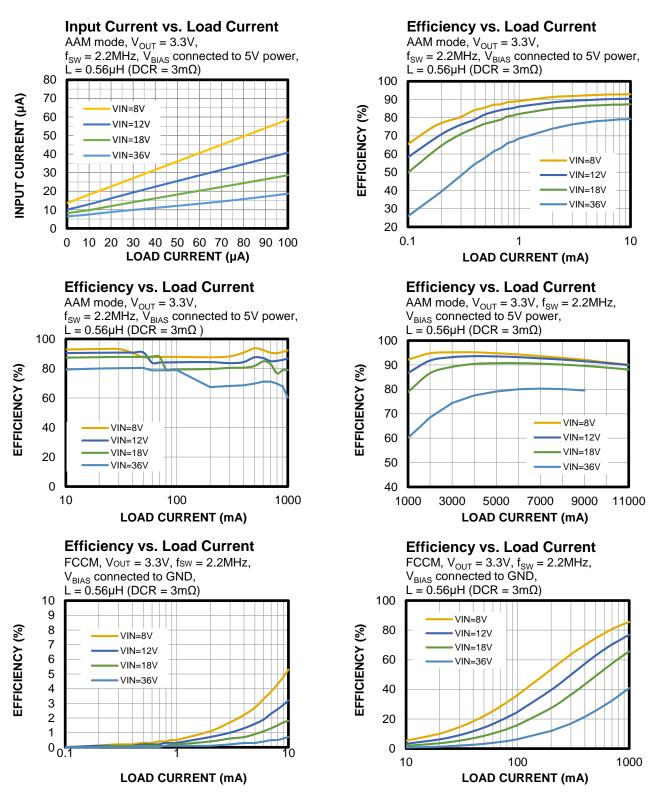




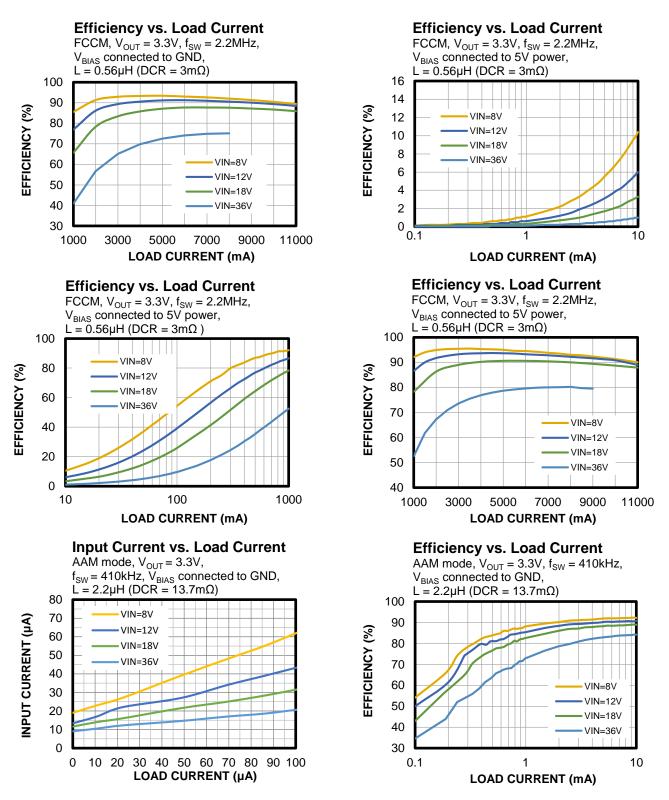




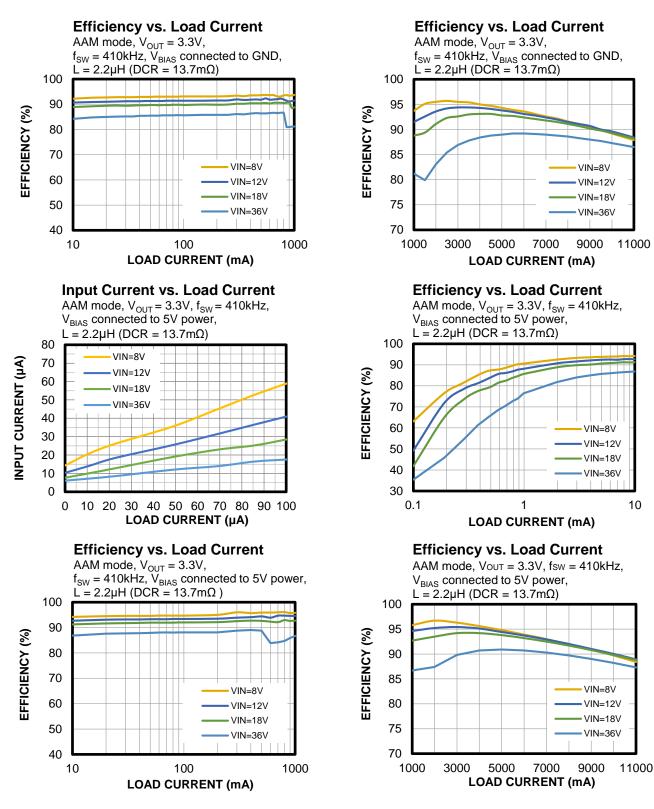




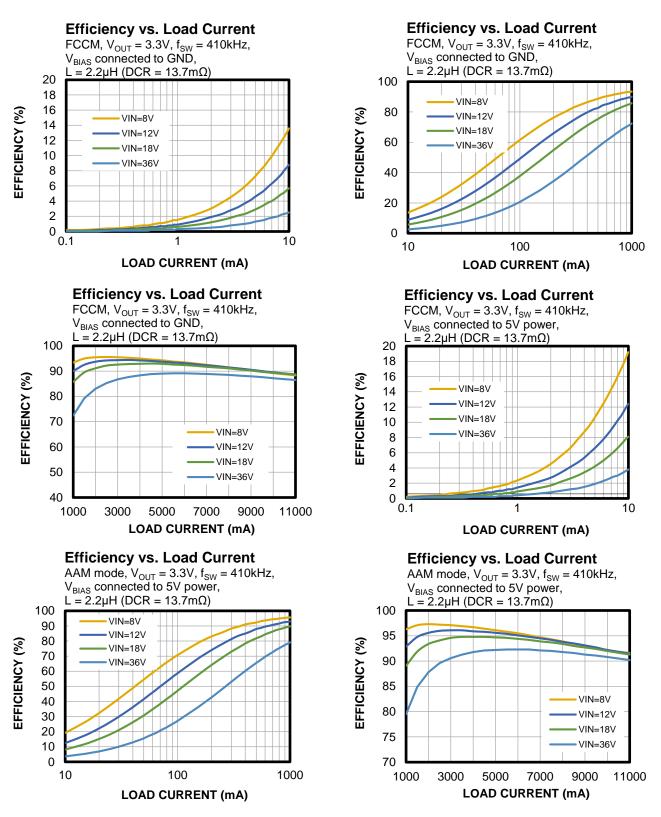






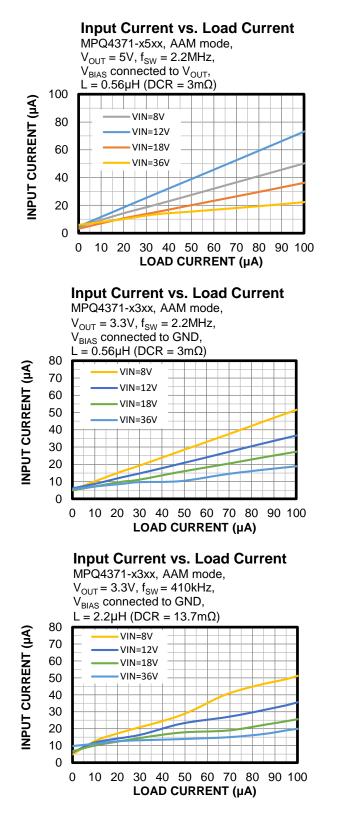




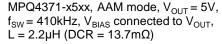


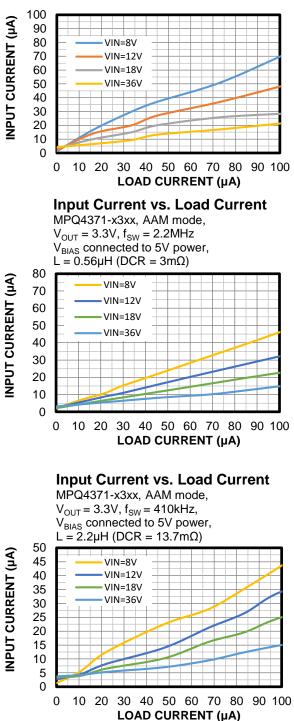


 $V_{IN} = 12V$, $V_{OUT} = 5V$, $f_{SW} = 2.2MHz$, $L = 0.56\mu$ H (DCR = $3m\Omega$), $T_A = 25^{\circ}$ C, unless otherwise noted.

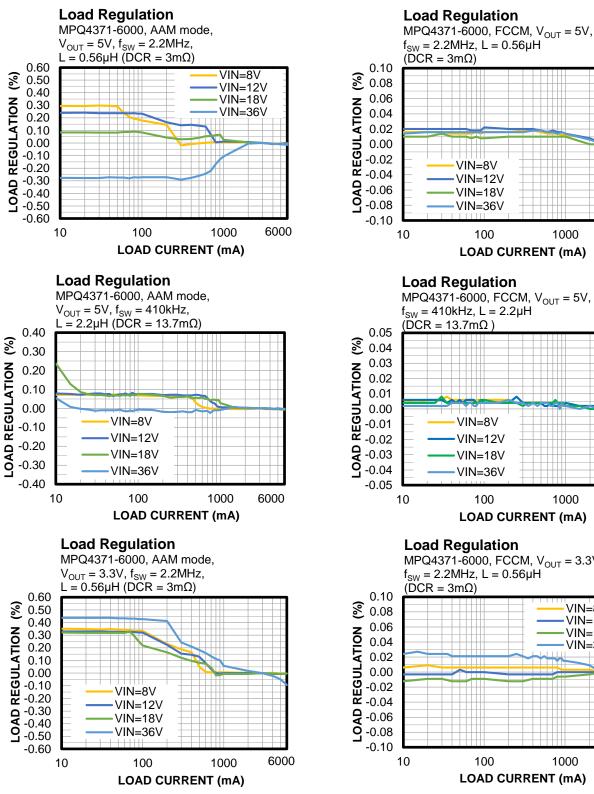


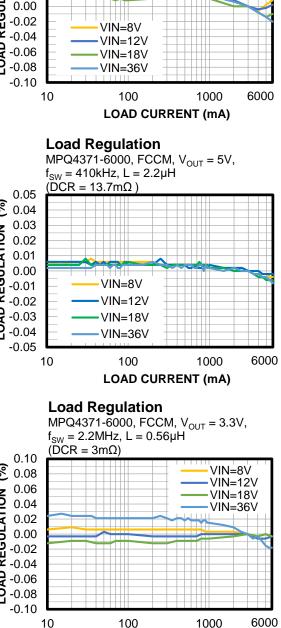
Input Current vs. Load Current for



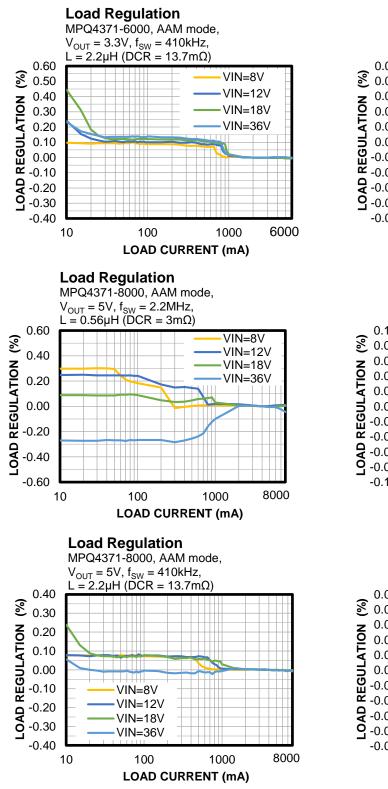


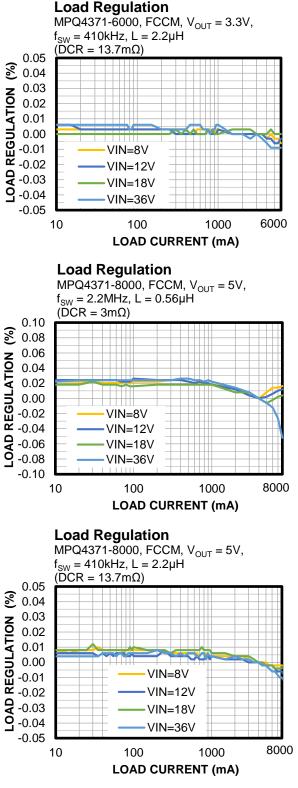




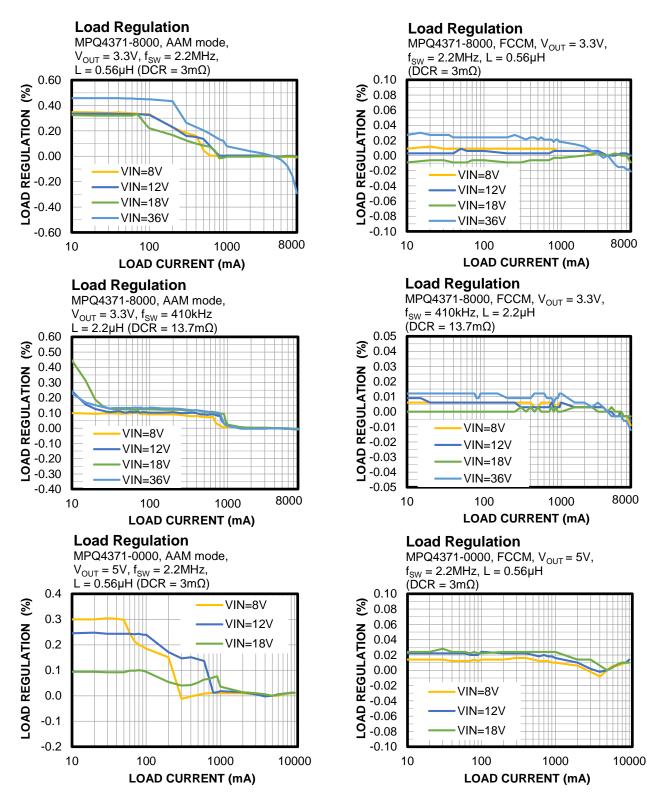














100

100

1000

1000

1000

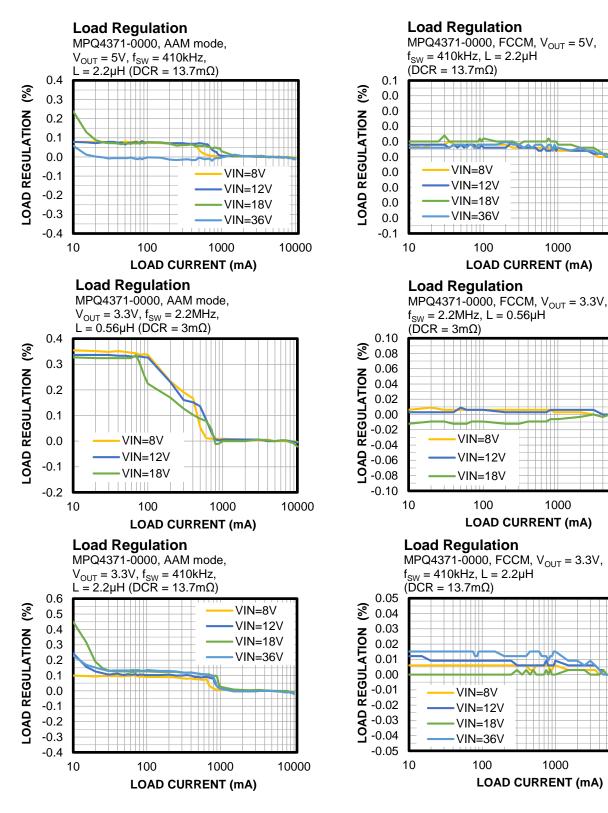
LOAD CURRENT (mA)

10000

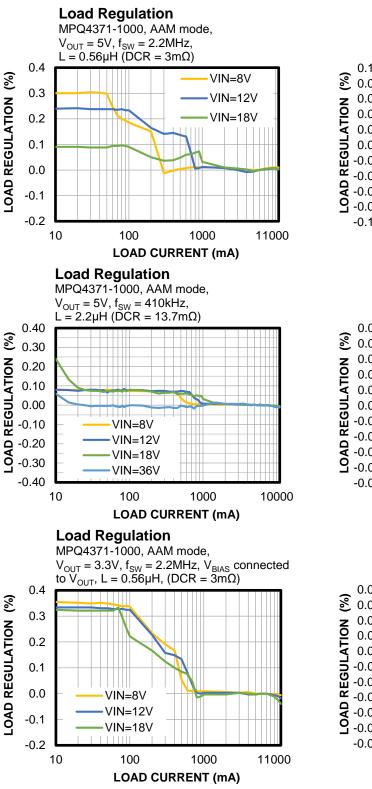
10000

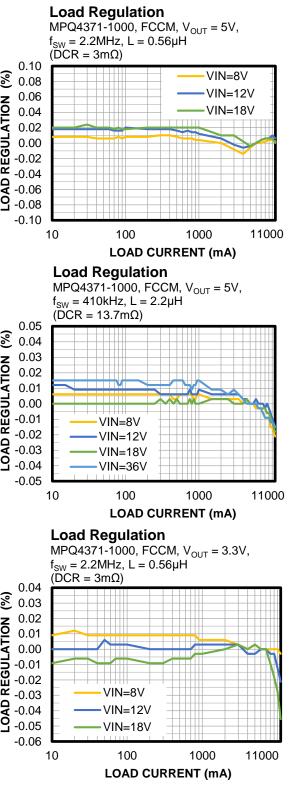
10000

TYPICAL PERFORMANCE CHARACTERISTICS (continued)



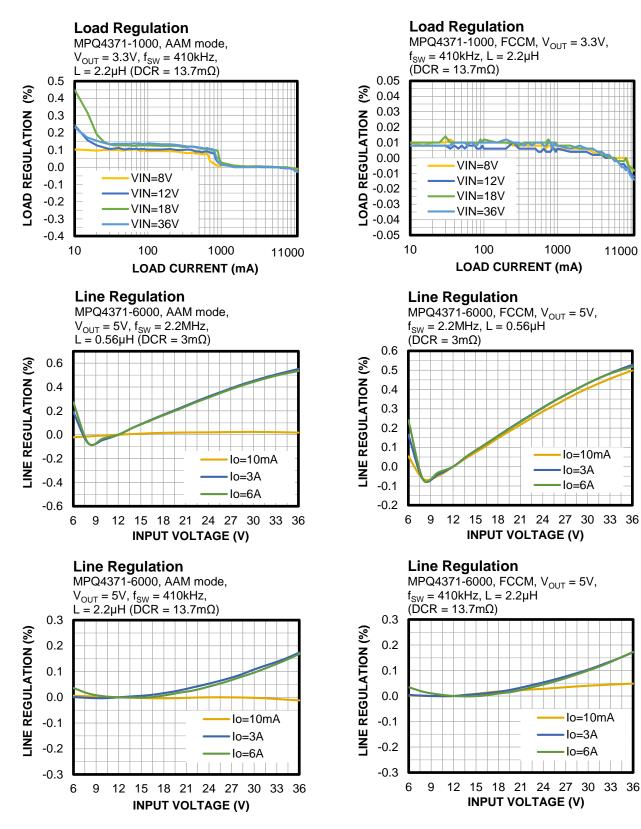






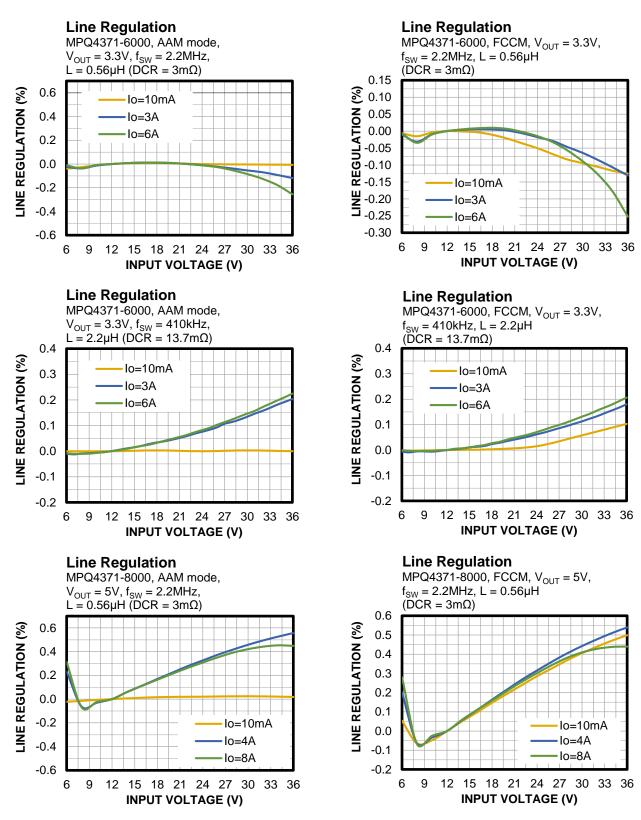


 $V_{IN} = 12V$, $V_{OUT} = 5V$, $f_{SW} = 2.2MHz$, $L = 0.56\mu H$ (DCR = $3m\Omega$), $T_A = 25^{\circ}C$, unless otherwise noted.

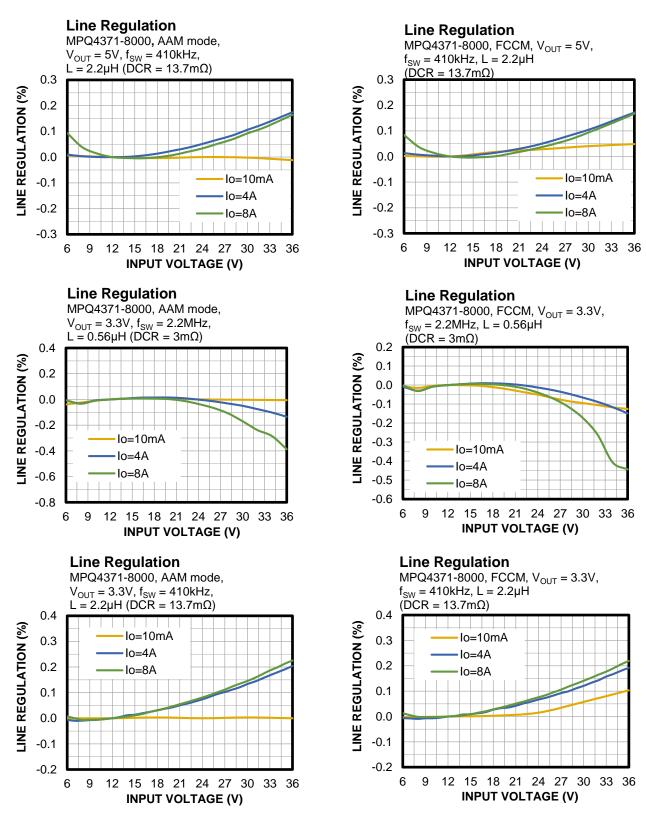


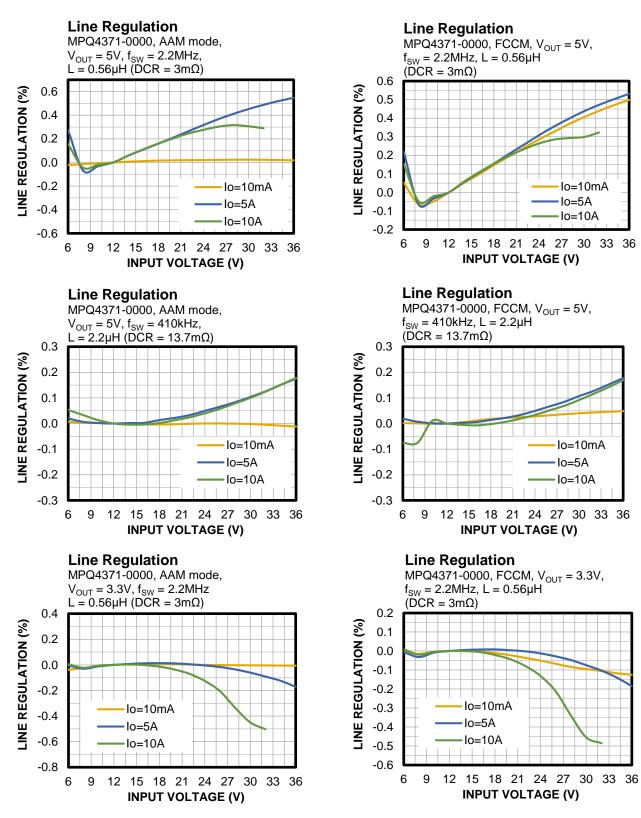
11000



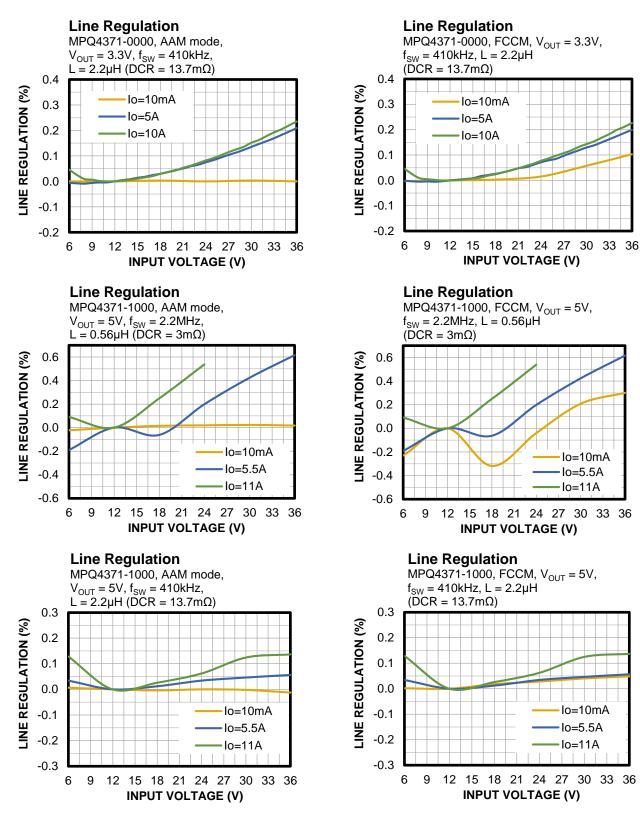






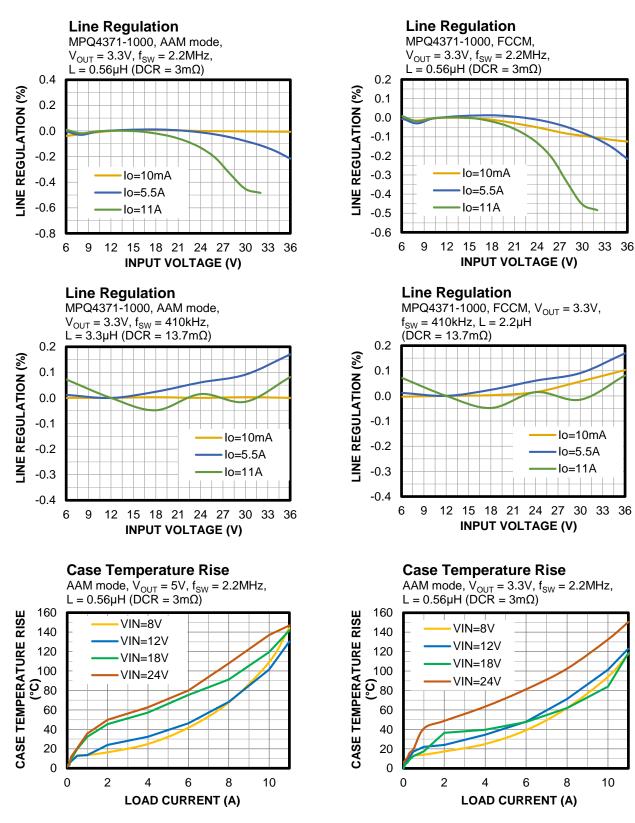






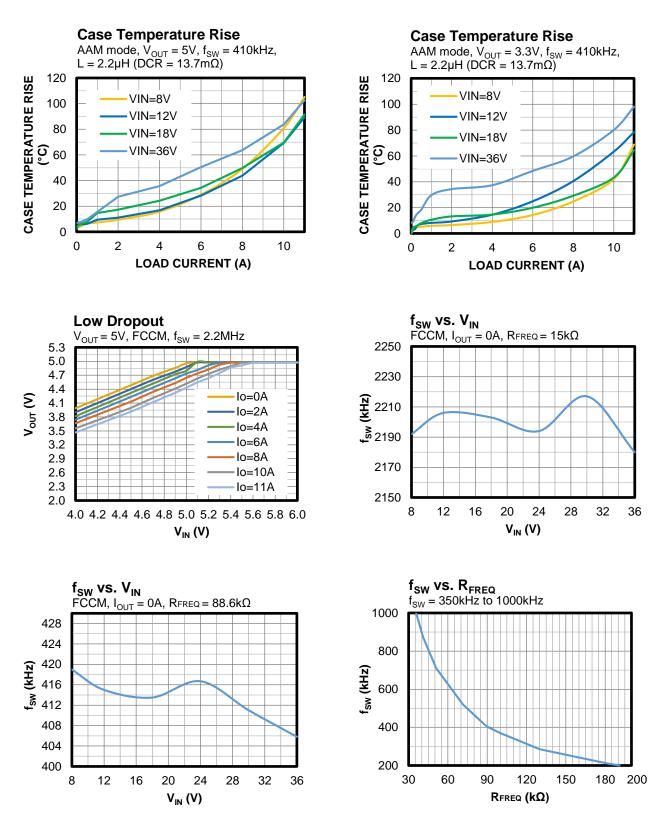


 $V_{IN} = 12V$, $V_{OUT} = 5V$, $f_{SW} = 2.2MHz$, $L = 0.56\mu H$ (DCR = $3m\Omega$), $T_A = 25^{\circ}C$, unless otherwise noted.

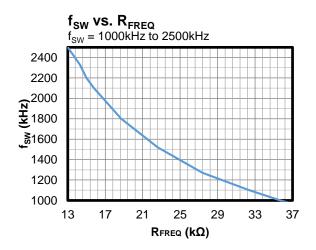


10



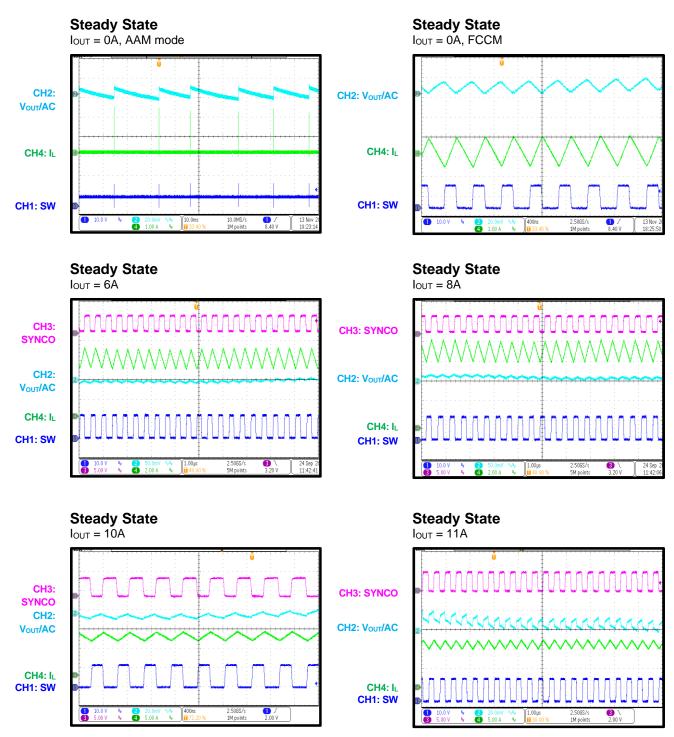






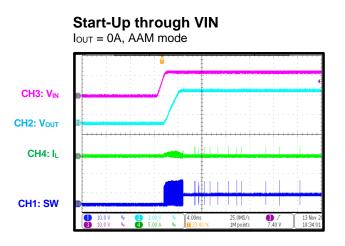


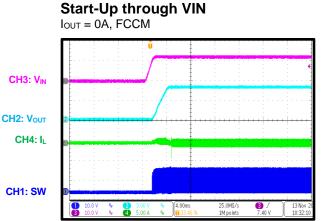
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.



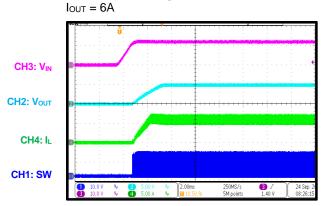


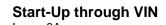
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

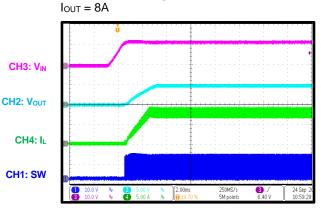


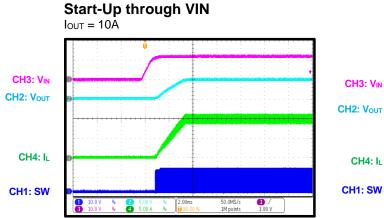


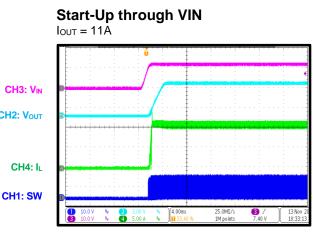
Start-Up through VIN





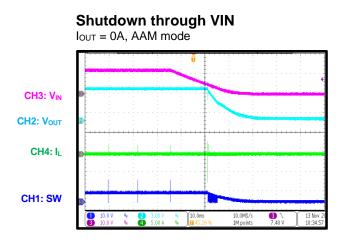


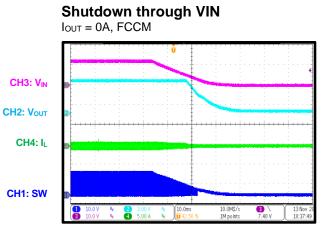




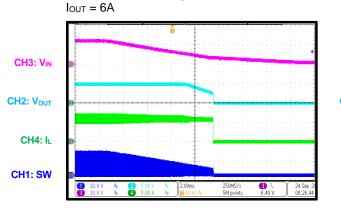


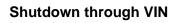
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

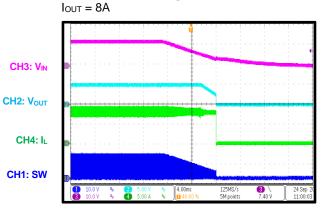


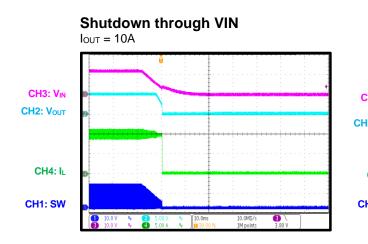


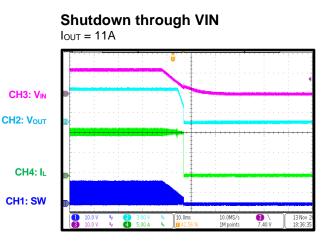
Shutdown through VIN







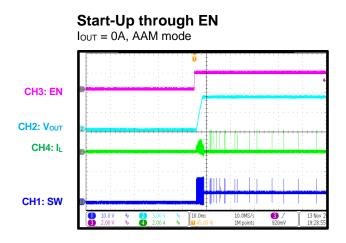


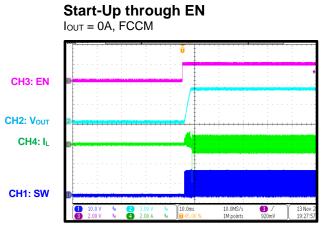


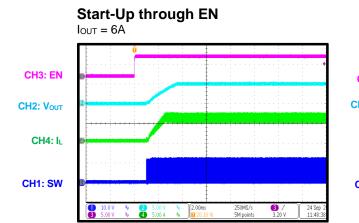
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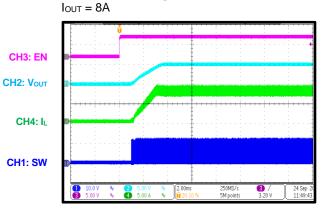
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

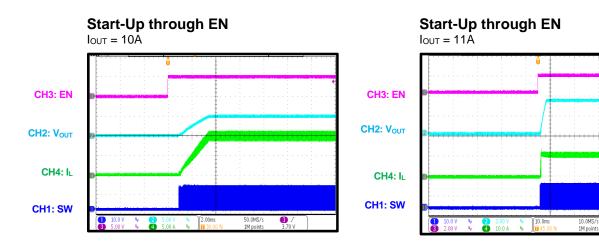






Start-Up through EN





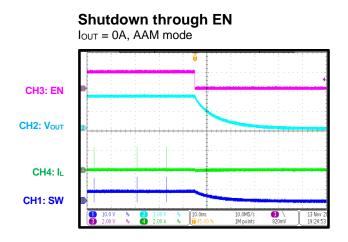


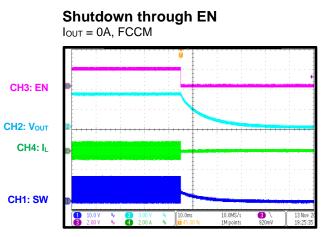
13 No 19:2

3 /



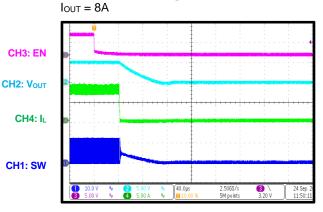
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

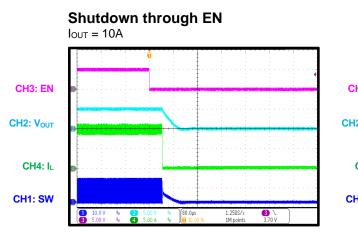


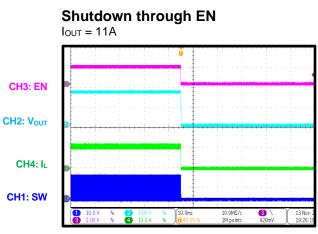


CH3: EN CH3: EN CH2: Vour CH4: IL CH1: SW Out = 6A Out = 70 Out = 70Out =

Shutdown through EN

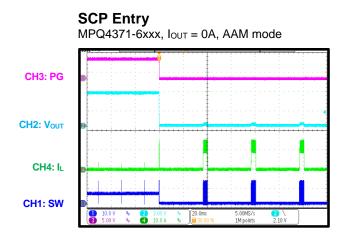


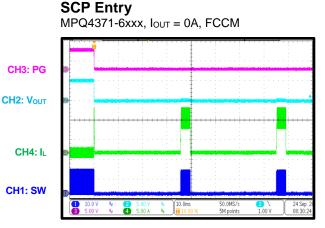




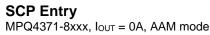


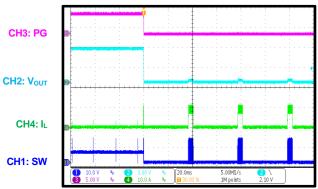
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

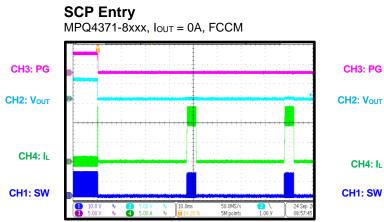


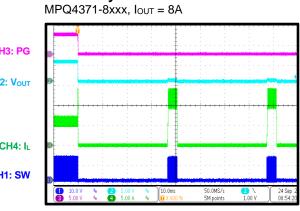


SCP Entry MPQ4371-6xxx, lour = 6A CH3: PG CH2: Vour CH4: lL CH1: SW CH1: SW CH1: SW CH2: Vour CH4: lL CH1: SW CH2: Vour







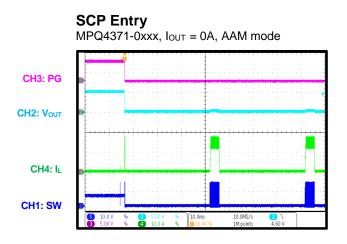


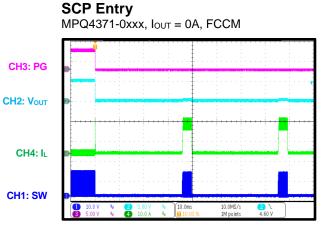
SCP Entry

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 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.





 SCP Entry MPQ4371-0xxx, Iout = 10A, FCCM

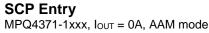
 CH3: PG

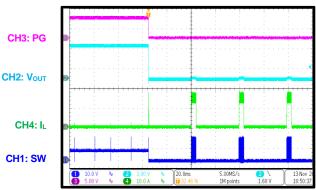
 CH2: Vout
 CH4: IL

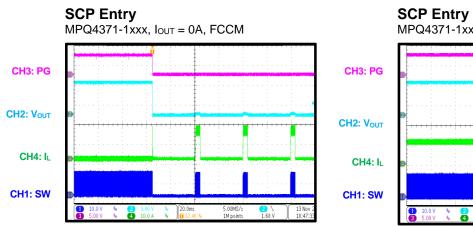
 CH4: IL
 0

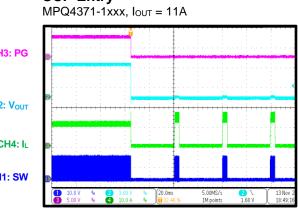
 CH1: SW
 0

 0
 100V
 0



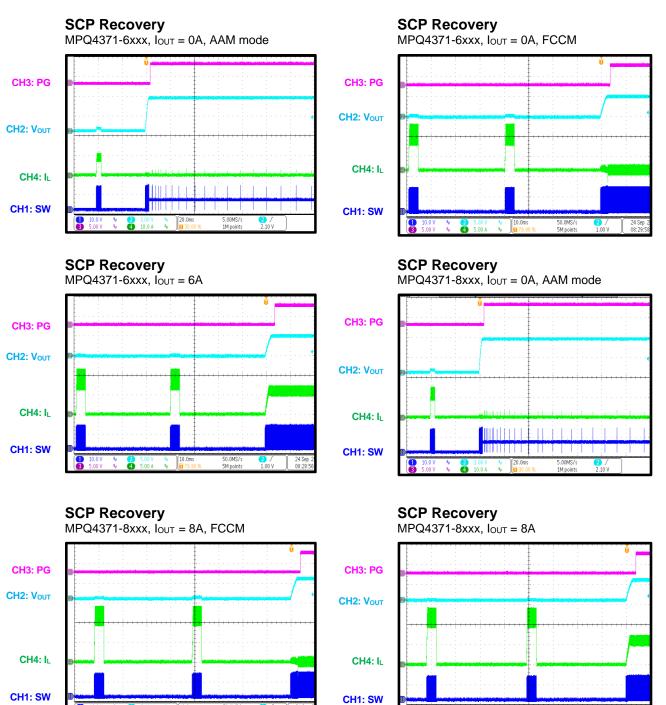








 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

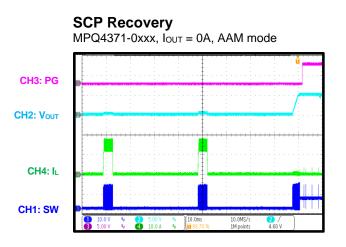


50.0MS 5M poir

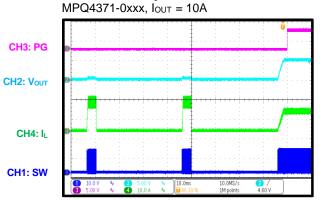
2 / 1.00 V

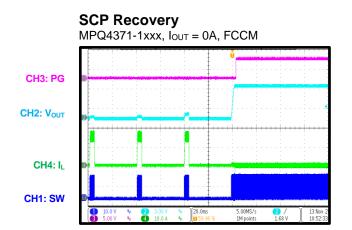


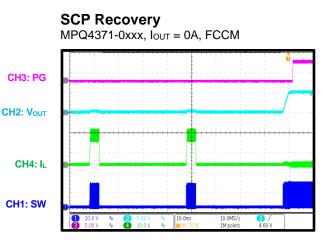
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.



SCP Recovery

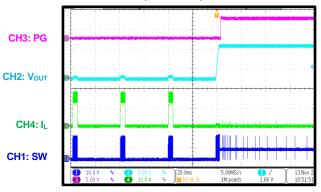




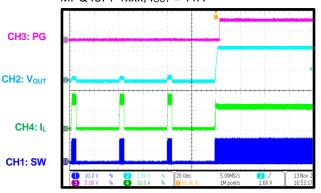


SCP Recovery

MPQ4371-1xxx, Iout = 0A, AAM mode

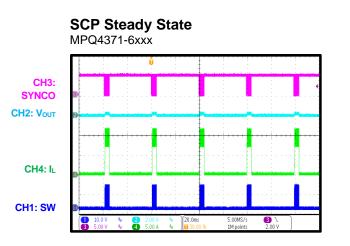


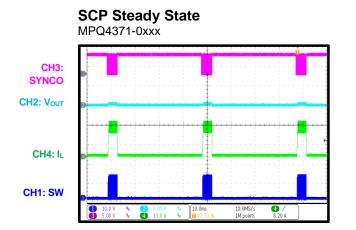
SCP Recovery MPQ4371-1xxx, Iout = 11A



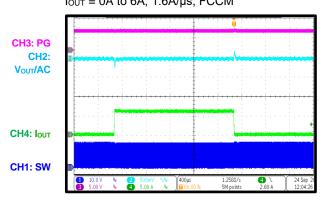


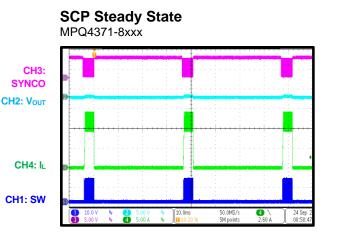
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.



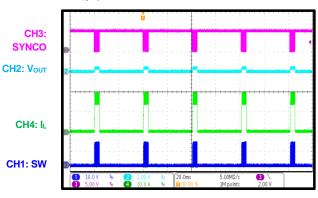


Load Transient Response Iout = 0A to 6A, 1.6A/µs, FCCM

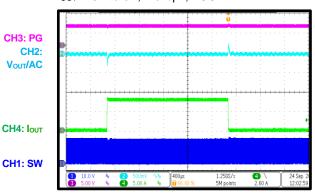




SCP Steady State

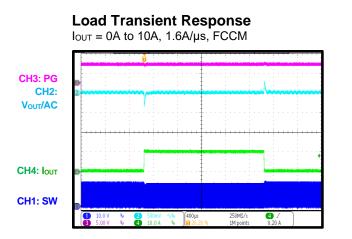


Load Transient Response Iout = 0A to 8A, 1.6A/µs, FCCM



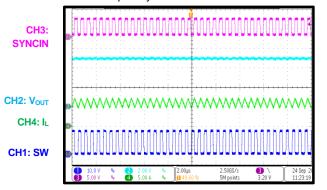


 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

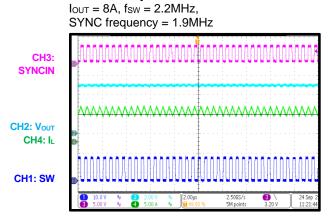


SYNCIN Operation

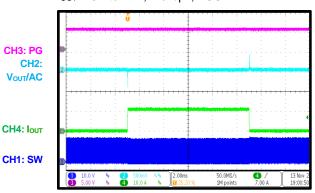
 $I_{OUT} = 6A$, $f_{SW} = 2.2MHz$, SYNC frequency = 1.9MHz



SYNCIN Operation

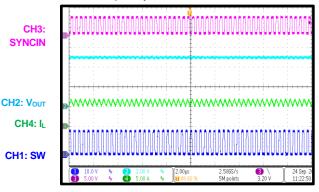


Load Transient Response Iout = 0A to 11A, 1.6A/µs, FCCM



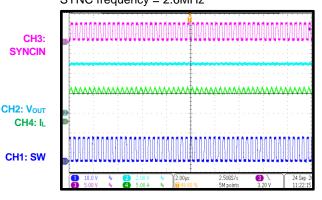
SYNCIN Operation

 $I_{OUT} = 6A, f_{SW} = 2.2MHz,$ SYNC frequency = 2.6MHz



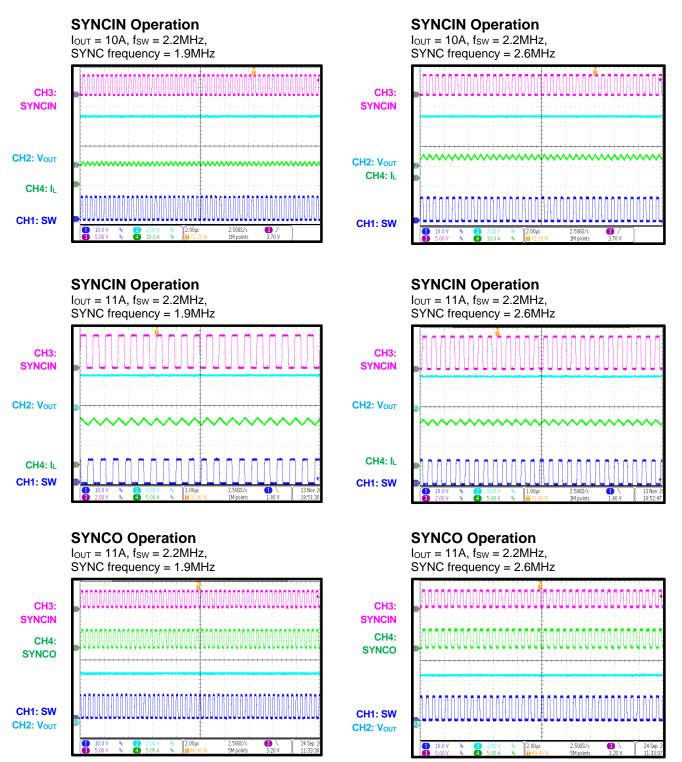
SYNCIN Operation

 $I_{OUT} = 8A$, $f_{SW} = 2.2MHz$, SYNC frequency = 2.6MHz



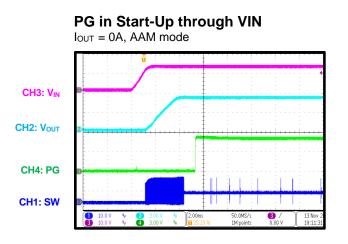


 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_{A} = 25°C, unless otherwise noted.

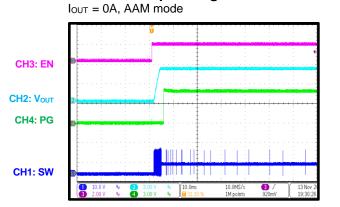




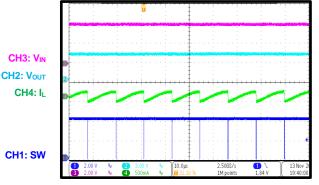
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_{A} = 25°C, unless otherwise noted.

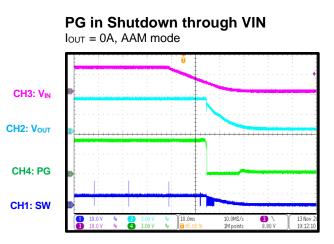


PG in Start-Up through EN

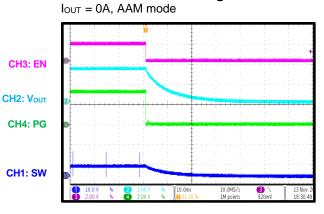






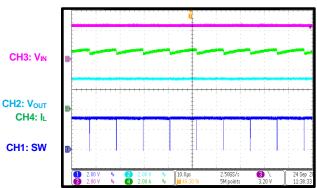


PG in Shutdown through EN



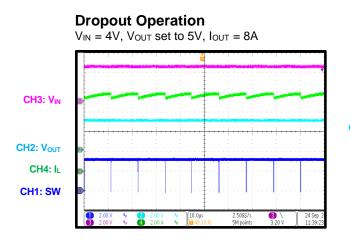
Dropout Operation

VIN = 4V, VOUT set to 5V, IOUT = 6A



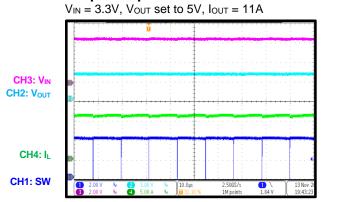


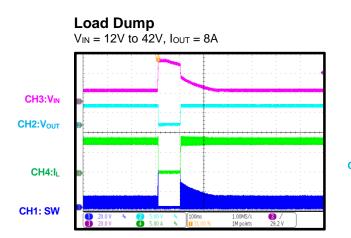
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

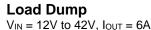


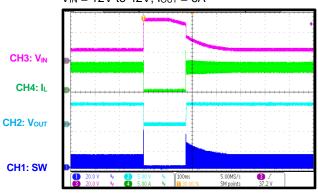
CH3: VN CH2: Vour CH4: IL CH1: SW

Dropout Operation



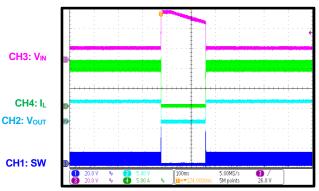






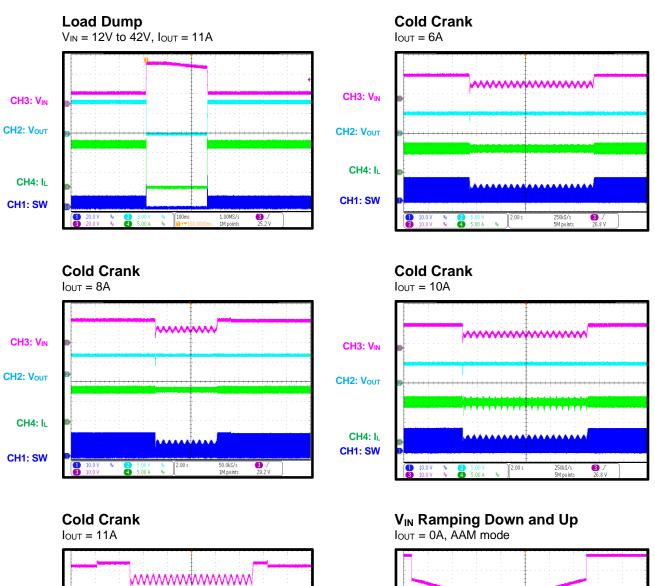
Load Dump

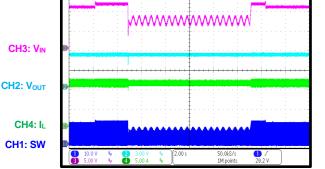
 $V_{IN} = 12V$ to 42V, $I_{OUT} = 10A$

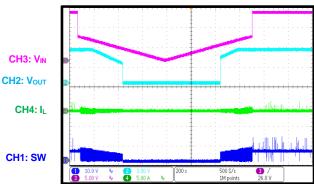




 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

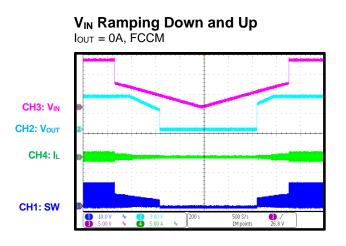


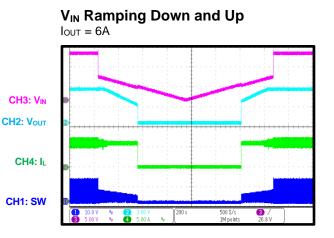






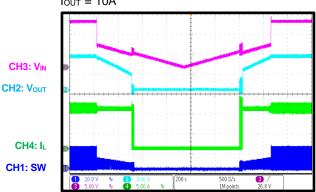
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

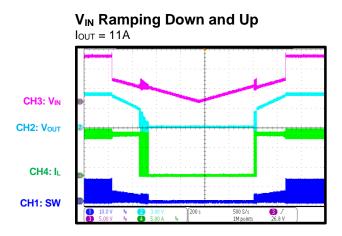




CH3: V_{IN} Ramping Down and Up $I_{OUT} = 8A$ CH3: V_{IN} CH2: V_{OUT} CH4: I_L CH1: SW $O(1) = 100^{V}$ V O(1) $O(2) = 100^{V}$ V O(2) $O(2) = 100^{V}$ V $O(2) = 100^{V}$ V O(2)O(2) =

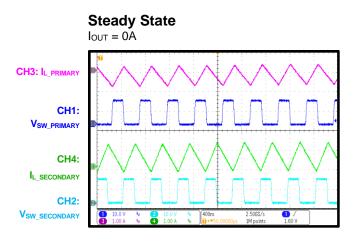


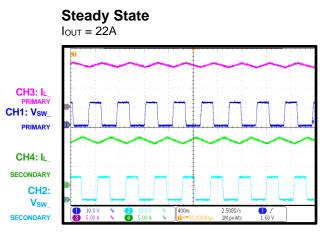






 V_{IN} = 12V, V_{OUT} = 5V, dual-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.





Start-Up through VIN Iour = 22A CH1: V_{IN} CH2: Vour CH3: V_IN IL PRIMARY

CH4: Il_secondary

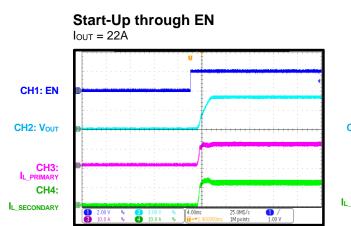
10.0 V

4 10.0 A

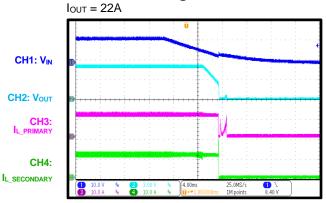
CH1: VIN

CH2: VOUT

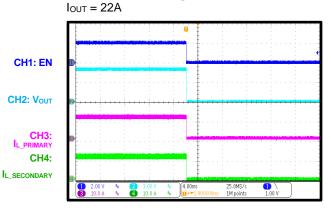
CH3: IL_PRIMARY



Shutdown through VIN

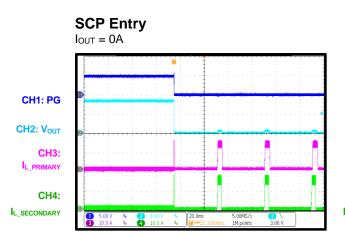


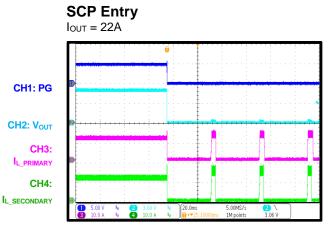
Shutdown through EN

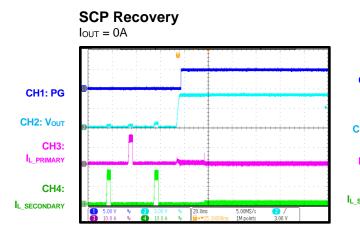




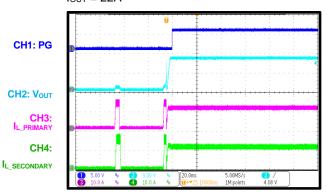
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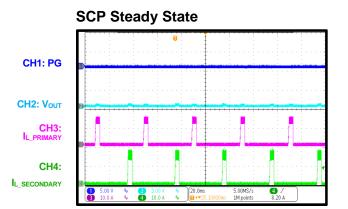




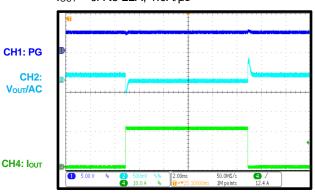






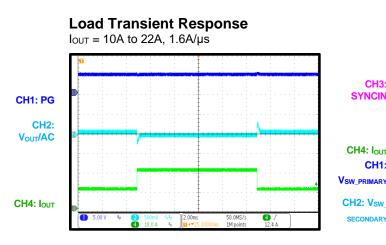


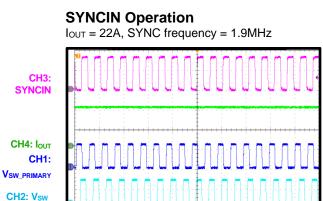
Load Transient Response Iout = 0A to 22A, 1.6A/µs



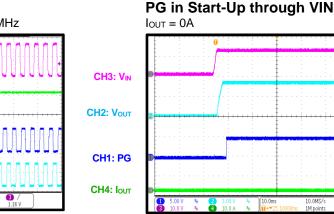


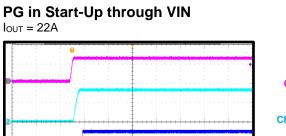
 $V_{IN} = 12V$, $V_{OUT} = 5V$, dual-phase, L = 0.56µH, $f_{SW} = 2.2MHz$, AAM mode, $T_A = 25^{\circ}C$, unless otherwise noted.





SYNCIN Operation IOUT = 22A, SYNC frequency = 2.6MHz CH3: **SYNCIN** CH4: IOUT CH1: VSW_PRIMARY CH2: V_{SW_SECONDARY} 3 / 1.16

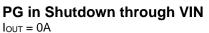




10.0ms

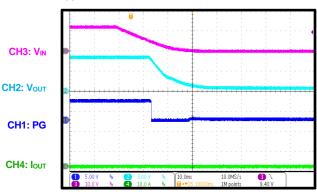
10.0MS/: 1M point:

3.



10.0MS/

8.



CH3: VIN

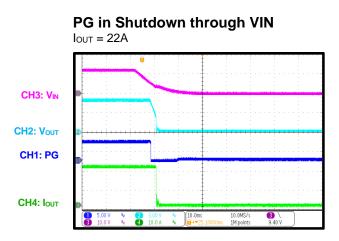
CH2: VOUT

CH1: PG

CH4: IOUT



 V_{IN} = 12V, V_{OUT} = 5V, dual-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.



PG in Start-Up through EN

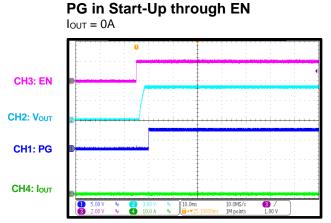
IOUT = 22A

CH3: EN

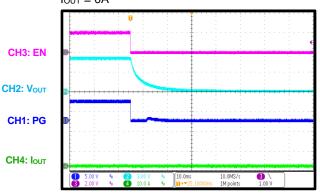
CH2: VOUT

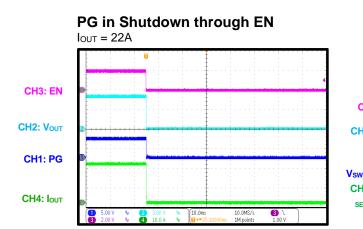
CH1: PG

CH4: IOUT



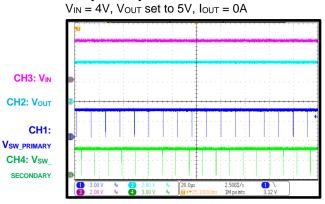
PG in Shutdown through EN Iout = 0A





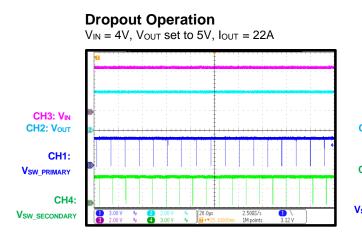
10.0MS 1M poin **3** J

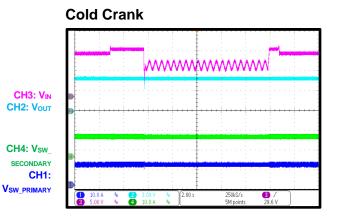
Dropout Operation



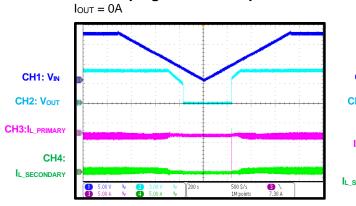


 V_{IN} = 12V, V_{OUT} = 5V, dual-phase, L = 0.56µH, f_{SW} = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted.

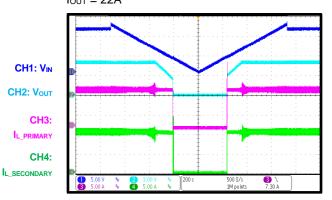




V_{IN} Ramping Down and Up

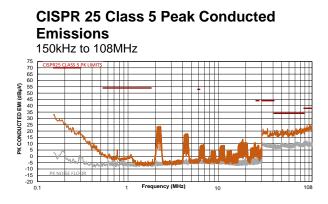


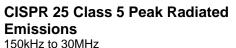
V_{IN} Ramping Down and Up Iout = 22A

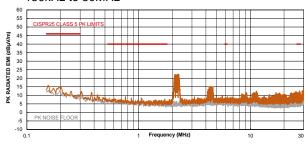




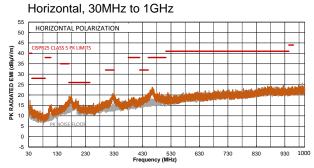
 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH $^{(12)},\,f_{SW}$ = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted. $^{(13)}$

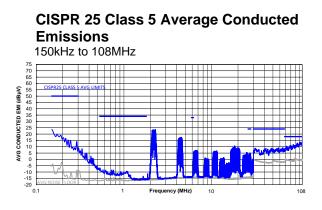




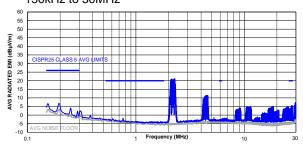


CISPR 25 Class 5 Peak Radiated Emissions

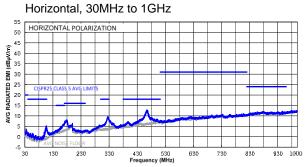






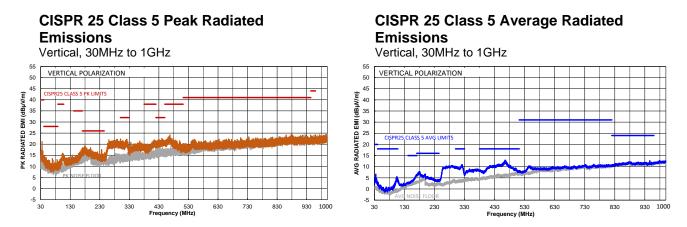


CISPR 25 Class 5 Average Radiated Emissions



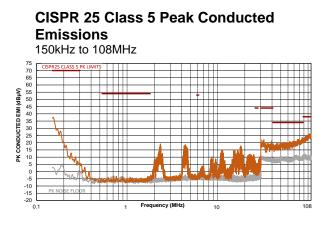


 V_{IN} = 12V, V_{OUT} = 5V, single-phase, L = 0.56µH $^{(12)},\,f_{SW}$ = 2.2MHz, AAM mode, T_A = 25°C, unless otherwise noted. $^{(13)}$

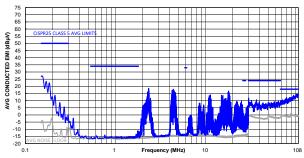




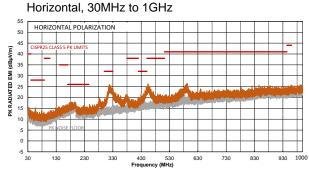
 V_{IN} = 12V, V_{OUT} = 5V, dual-phase, L = 0.56µH $^{(12)}$, f_{SW} = 2.2MHz, AAM mode, T_{A} = 25°C, unless otherwise noted. $^{(14)}$

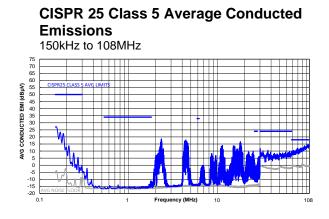




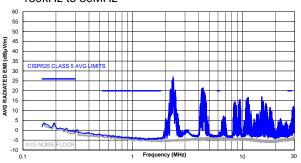


CISPR 25 Class 5 Peak Radiated Emissions

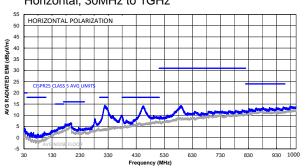




CISPR 25 Class 5 Average Radiated Emissions 150kHz to 30MHz

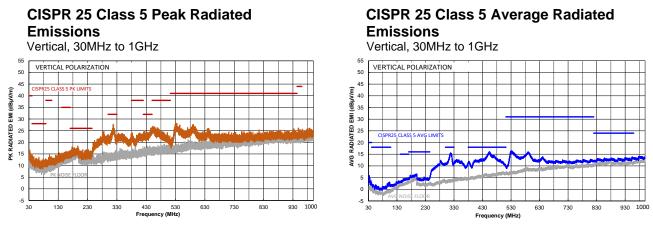


CISPR 25 Class 5 Average Radiated Emissions Horizontal, 30MHz to 1GHz





 V_{IN} = 12V, V_{OUT} = 5V, dual-phase, L = 0.56µH $^{(12)}$, f_{SW} = 2.2MHz, AAM mode, T_{A} = 25°C, unless otherwise noted. $^{(14)}$



Notes:

12) Inductor part number: XEL6030-561MEB/C. DCR = 3mΩ.

13) The EMC test results are based on the application circuit with EMI filters (see Figure 19 on page 77).

14) The EMC test results are based on the application circuit with EMI filters (see Figure 23 on page 79).



FUNCTIONAL BLOCK DIAGRAMS

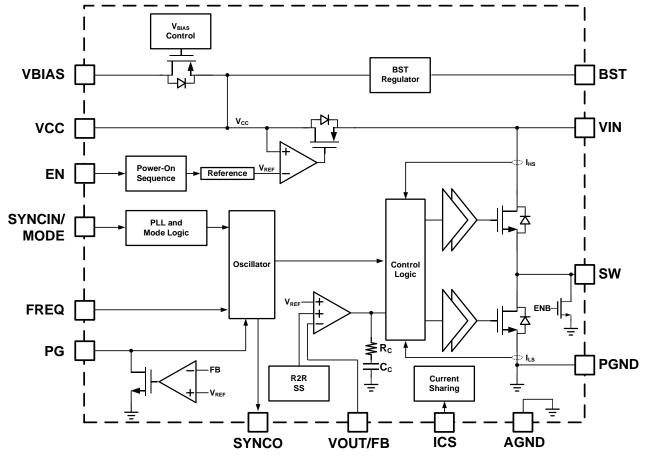


Figure 3: Functional Block Diagram for Adjustable-Output Version



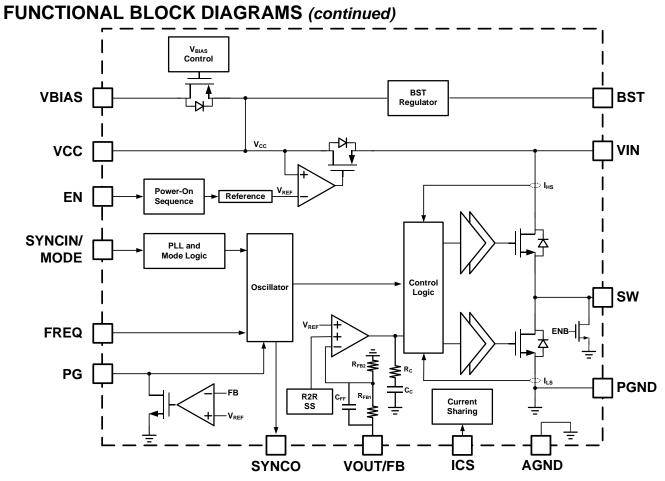


Figure 4: Functional Block Diagram for Fixed-Output Version



TIMING SEQUENCE DIAGRAM

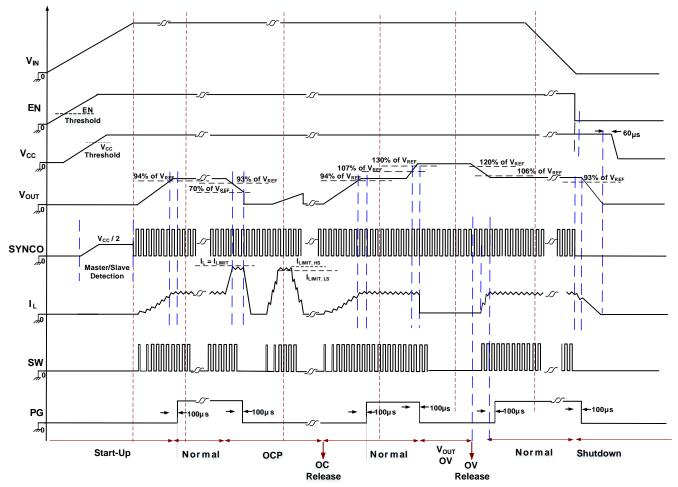


Figure 5: Timing Sequence Diagram



OPERATION

The MPQ4371 family of buck converters are configurable-frequency (200kHz to 2.5MHz), synchronous, step-down switching regulators with integrated low on resistance HS-FETs and LS-FETs. The family covers a 6A to 11A output current (I_{OUT}) range and employs zero-delay pulse-width modulation (PWM) (ZDPTM) control, an MPS-exclusive technology that delivers fast transient response while reducing external capacitor count. In addition, it maintains the fixed fsw, and its low operational quiescent current makes this device well-suited for battery-powered applications.

Zero-Delay PWM (ZDP[™]) Control

Automotive applications generally require fixedfrequency operation to reduce EMI concerns, but with fixed-frequency traditional topologies control have major limitations. For example, voltage mode is difficult to compensate in automotive environments, while peak current mode control struggles to keep up with stringent modern system-on-chip (SoC) transient requirements without excessive output capacitance. With these requirements in mind, the MPQ4371 features fixed-frequency ZDP™ control.

ZDP[™] control combines current information with the hysteretic-style output voltage control in a clocked system. This provides an optimal transient response while maintaining a high phase margin across a wide variety of operating conditions and external component values. This control maintains superior EMI performance. The improved transient response reduces output capacitor requirements and lowers system cost. Trailing edge modulation facilitates a narrow minimum on time for high conversion ratio applications.

At the beginning of the PWM cycle, the high-side MOSFET (HS-FET) turns off, and the low-side MOSFET (LS-FET) turns on immediately until the control signal reaches the COMP voltage (V_{COMP}). The HS-FET remains off for at least 80ns at the beginning of the cycle.

Light-Load Operation

Under light-load conditions, the MPQ4371 can operate in two different operation modes by setting the state of the SYNCIN/MODE pin.

The MPQ4371 works in forced continuous conduction mode (FCCM) when the SYNCIN/MODE pin is pulled above 1.4V or an external clock is used. In FCCM, the MPQ4371 works with a fixed frequency from the no-load to full-load range. The MPQ4371 has a reverse current limit to prevent the negative current from dropping too low and damaging the components. Once the negative inductor current reaches the reverse current limit, the HS-FET immediately turns on, and the LS-FET turns off. The advantages of FCCM are its constant frequency and lower output voltage ripple at light loads. FCCM also has a better response to sudden load changes.

The MPQ4371 works in advanced asynchronous modulation (AAM) mode when the SYNCIN/MODE pin is pulled below 0.4V. AAM mode cannot be entered until soft start has finished. AAM mode optimizes efficiency under light-load and no-load conditions.

In AAM mode, the LS-FET emulates a diode and the HS-FET has a fixed one-shot on-time to charge the inductor and regulate the output. As the load decreases, the interval between each one-shot increases. When this interval is longer than 8µs, the MPQ4371 enters sleep mode, which turns off some internal circuits and extends the on time to achieve an ultra-low quiescent current. When the load increases, and the interval becomes shorter than 6us, the device exits sleep mode and re-enters AAM mode. The part can exit AAM mode immediately if the SYNCIN/MODE pin goes high. If there is a fault (e.g. over-current, over-temperature), then the MPQ4371 does not disable the internal circuits in sleep mode.

Start-Up and Shutdown

If both the input voltage (V_{IN}) and EN exceed their appropriate thresholds, the chip starts. The reference block starts first, generating a stable reference voltage and currents, and then the internal regulator is enabled. The regulator provides a stable supply for the remaining circuitries.

While the internal supply rail is up, an internal timer holds the HS-FET and LS-FET off for about 100µs to blank the start-up glitches. When the



soft-start block is enabled, it first holds its softstart output low to ensure that the remaining circuits are ready, and then slowly ramps up.

Four events shut down the chip: EN going low, V_{IN} going low, thermal shutdown and V_{IN} overvoltage (OV) shutdown. In the shutdown procedure, the signaling path is blocked first to avoid any fault triggering, then V_{COMP} and the internal supply rail are pulled down. The floating driver is not subject to this shutdown command, but its charging path is disabled.

Error Amplifier (EA)

The error amplifier (EA) compares the FB pin's voltage (V_{FB}) with the internal reference (0.6V). The output of the EA is then compared to V_{FB} again. The output of this comparator is compared to the current information to control the power MOSFET's duty cycle.

Low-Dropout (LDO) Mode

When V_{IN} drops close to the output voltage (V_{OUT}) and the device detects the minimum off time (100ns) that the HS-FET is using, the MPQ4371 is in low-dropout mode. The MPQ4371 reduces f_{SW} to achieve a high duty cycle. When f_{SW} drops to about 100kHz, the minimum off time is about 50ns to achieve a higher duty cycle. During soft start, the MPQ4371 only enters low-dropout mode after 60% of the SS time has elapsed.

The effective duty cycle during the regulator's dropout period is mainly influenced by the voltage drop across the power MOSFET, the inductor's resistance, and the PCB resistance.

Frequency Spread Spectrum (FSS)

The MPQ4371 uses dual spread spectrum modulation. First, the MPQ4371 has a 15kHz modulating frequency (f_{MOD1}) with \leq 128 steps and a triangular profile to spread the internal oscillator frequency across a ±6.2% window. The number of steps varies with the configured oscillator frequency so that the exact same f_{SW} steps cycle by cycle.

A second modulating frequency (f_{MOD2}) of 120kHz varies the oscillator frequency across a ±2.5% window with a maximum of 16 steps. This higher modulating frequency improves the effect of FSS across the high-frequency EMI measurements, where the resolution bandwidth (RBW) is 120kHz (see Figure 6).

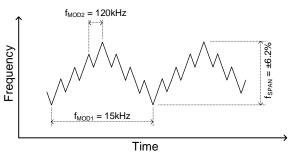


Figure 6: FSS

The emission power of the fundamental f_{SW} and its harmonics is distributed into smaller pieces by creating side-bands when modulating f_{SW} with the triangle modulation waveform. This significantly reduces the amplitude of individual EMI spikes (also called spurs).

Soft Start

The MPQ4371 has an internal soft start implemented to prevent the converter's output voltage from overshooting during start-up. The default soft-start duration is 4ms.

Pre-Biased Start-Up

When the MPQ4371 starts up and V_{FB} is < 100% of its target, the MPQ4371 initiates soft start.

If V_{FB} is between 100% and 130% of its target at start-up while in FCCM, this means that the output has a pre-biased voltage. Neither the HS-FET nor LS-FET turn on until the internal soft start process is 80% complete. Then the MPQ4371 starts switching and regulates the output before soft start finishes.

If V_{FB} exceeds 130% of its target at start-up, the MPQ4371 start to slowly discharge the output through the discharging FET on SW. Once V_{FB} reaches 120% of its target, the MPQ4371 starts the internal soft start and operates following the pre-biased start-up process, as explained in the previous paragraph.

SYNCIN and SYNCO

 $f_{\rm SW}$ can be synchronized to the rising edge of a clock signal applied at the SYNCIN/MODE pin. The recommended SYNCIN frequency range is between 200kHz and 2.5MHz. The SYNCIN frequency should be set to match the internal $f_{\rm SW}$ with a $\pm 10\%$ tolerance.

The SYNCO pin provides a clock signal that is in phase with the internal oscillator when there is no SYNCIN signal, or a clock signal in phase



with SYNCIN. Figure 7 shows when an external clock signal is applied at SYNCIN. This makes it simple to enable a dual-phase interleaving configuration.

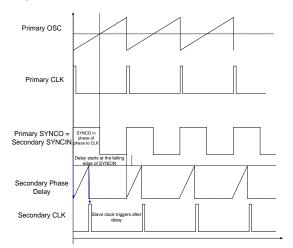


Figure 7: SYNCIN and SYNCO Scheme

Primary/Secondary Selection and Multi-Phase Function

"Primary" and "secondary" are terms are used to describe the role of the different ICs in a multiphase power converter. The primary device generates a clock signal to which the secondary device is synchronized, and it also asserts PG based on the output regulation.

The device detects the SYNCO pin's status during start-up to configure the primary and secondary selection. If the chip detects a high impendence on the SYNCO pin, the device is configured to be a primary device. If the SYNCO pin is pulled high (connected to VCC or an external voltage) or low (connected to GND), the device is configured to be a secondary device.

To work in a multi-phase topology, The VOUT/FB pins of the devices must be connected together directly or through feedback resistors.

The ICS pins must be connected together, and a local, lower-value capacitor much be placed between each ICS pin and GND.

The primary device's SYNCO pin is connected to the SYNCIN/MODE pins of the secondary devices, which are interleaved. If the primary device's SYNCIN/MODE pin is used for mode selection, the secondary devices' SYNCO pins can be tied to the primary device's SYNCIN/MODE pin; pull SYNCIN/MODE low to select AAM mode, or pull it high for FCCM. If the primary device's SYNCIN/MODE pin is applied with the external clock signal to synchronize the internal oscillator frequency, the SYNCO pins of the secondary devices can only be pulled high or low, and they cannot be connected to the primary device's SYNCN/MODE pin. With multiphase applications, avoid floating the primary device's SYNCIN/MODE pin. or connect it to GND/VCC through a larger resistor (>20k Ω).

Pull the PG pin to a power source through a resistor or leave it floating if it is not used for the primary device. For secondary devices, connect a resistor to ground on the PG pin to set the phase delay and allow for simple multi-phase operation; Connect PG directly to GND to select no delay on the SYNCIN signal for secondary phase.

Figure 8 shows a dual-phase configuration.

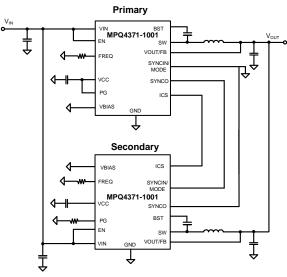


Figure 8: Dual-Phase Configuration

Figure 9 on page 67 shows a 4-phase configuration.



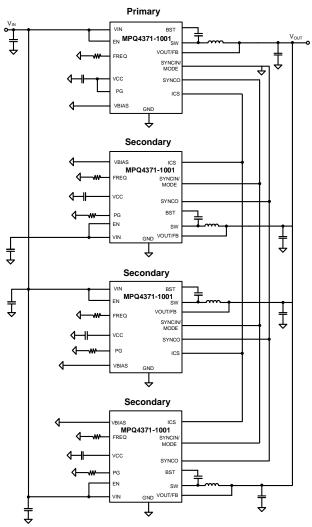


Figure 9: 4-Phase Configuration

For multi-phase applications, start with AAM mode then change to FCCM after the PG signal of the primary phase pulls high.

Thermal Shutdown

Thermal shutdown is implemented to prevent the chip from thermal runaway. When the silicon die temperature exceeds its upper threshold (180°C), the MPQ4371 shuts down the power MOSFETs. When the temperature falls below the lower threshold (150°C), thermal shutdown is removed, so the chip is enabled again.

V_{IN} Over-Voltage Protection (OVP)

The MPQ4371 stops switching when V_{IN} exceeds its OV rising threshold (typically 38V). The device resumes normal regulation and switching when V_{IN} drops to its OV falling threshold (typically 37V). If the MPQ4371 is operating in sleep mode, this OVP function is turned off between the noswitching periods. The V_{IN} OVP function only works during the one-shot HS on time and detects if V_{IN} reaches the OVP threshold.

Peak and Valley Current Limit

Both the HS-FET and LS-FET have cycle-bycycle current-limit protection. When the inductor current (I_L) reaches the high-side peak current limit (typically 17.2A for the MPQ4371-0xxx) while the HS-FET is on, the HS-FET is forced off immediately to prevent the current from rising further. If there is an internal clock signal before the peak current limit is reached, the HS-FET also turns off.

When the LS-FET is on, the next clock's rising edge is held until I_{\perp} drops below the low-side valley current limit (typically 12A for the MPQ4371-0xxx). Then I_{\perp} can drop to a sufficiently low value when the HS-FET turns on again. This current limit scheme prevents current runaway if an overload or short-circuit event occurs.

Short-Circuit Protection (SCP)

If V_{OUT} drops below 93% of its nominal output and the EA's output is clamped, the MPQ4371 counts the valley current limit counter (LSOC) about 128 times and enters hiccup mode.

If V_{OUT} drops below 70% of its nominal output, the MPQ4371 counts the LSOC about 8 times then enters hiccup mode. The device restarts with a full soft start after about 32ms. This hiccup process repeats until the fault is removed.

During the hiccup period, when V_{FB} reaches 80% of internal reference, the part considers the SCP recovery action. In this scenario, the device reinitiates a soft start, which can prevents large output voltage spikes if the MPQ4371 recovers during the SCP period.

Output Over-Voltage Protection (OVP) and Discharge

If VOUT exceeds 130% of its nominal regulation value in non-sleep mode (e.g. FCCM), the MPQ4371 stops switching. Then an internal discharge path from SW to GND is activated to discharge VOUT. The discharge is disabled when VOUT drops back to 120% of its nominal value, and the device resumes switching when VOUT drops below the nominal output voltage.



If the device is operating in a sleep mode, the output OVP function is turned off, and the PG rising and falling thresholds are used to detect OVP. The discharge circuit is activated if V_{OUT} is exceeds 107% of its normal regulation value, and discharging is disabled when V_{OUT} drops back to 106% of its nominal value. The MPQ4371 resumes switching when V_{OUT} drops below its nominal value.

If Vout exceeds 130% of its nominal regulation value in a non-sleep mode (e.g. AAM mode or DCM) within 160 μ s, the MPQ4371 follows the non-sleep mode (e.g. CCM) function.

If the period is longer than 160µs, the MPQ4371 enters sleep mode, and the OVP threshold becomes 107% or 106% of the nominal value, which same as sleep mode OVP function.

Not only does output OVP trigger the discharge function; the output discharge function is also activated during EN shutdown.



APPLICATION INFORMATION

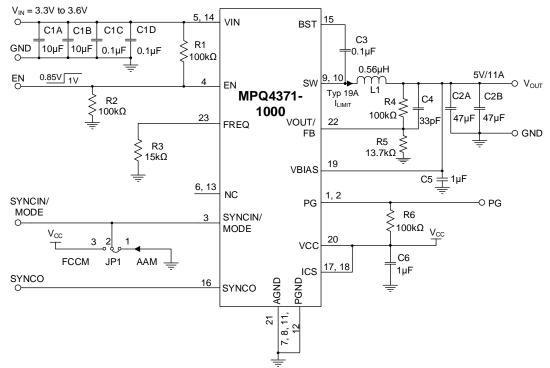


Figure 10: Typical Application Circuit for the MPQ4371	-1000 (Vout = 5V, fsw = 2.2MHz)
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	Table 1. Design Guide Index and Recommended values							
Pin #	Pin name	Component	Design Guide Index	Value				
1, 2	PG	R6	Power Good (PG) Indication or Phase Shift Setting (PG, Pins 1–2)	100kΩ				
3	SYNCIN/MODE	-	Sync Input and MODE Selection (SYNCIN/MODE, Pin 3)	-				
4	EN	R1, R2	Enable and VIN Under-Voltage Lockout (UVLO) (EN, Pin 4)	100kΩ,100kΩ				
5, 14	VIN	C1A, C1B, C1C, C1D	Selecting the Input Capacitors (VIN, Pins 5 and 14)	10μF, 10μF,0.1μF, 0.1μF				
6, 13	NC	N/A	N/A	-				
7, 8, 11, 12	PGND	-	GND Connection (PGND, Pins 7–8 and Pins 11– 12; AGND, Pin 21)	-				
9, 10	SW	L1, C2A, C2B	Selecting the Inductor and Output Capacitors (SW, Pins 9–10)	0.56μH,47μF, 47μF				
15	BST	C3	Floating Driver and Bootstrap Charging (BST, Pin 15)	0.1µF				
16	SYNCO	-	Sync Output (SYNCO, Pin 16)	-				
17, 18	ICS	-	Current Sharing (ICS, Pins 17–18)	-				
19	VBIAS	C5	Internal LDO Supply (VBIAS, Pin 19)	1µF				
20	VCC	C6	Internal LDO Supply (VCC, Pin 20)	1µF				
21	AGND	-	GND Connection (PGND, Pins 7–8 and Pins 11– 12; AGND, Pin 21)	-				
22	VOUT/FB	R4, R5, C4	Setting the Feedback (VOUT/FB, Pin 22)	100kΩ, 13.7kΩ, 33pF				
23	FREQ	R3	Setting the Switching Frequency (fsw) (FREQ, Pin 23)	15kΩ				

Table 1: Design Guide Index	and Recommended Values
-----------------------------	------------------------



Power Good (PG) Indication or Phase Shift Setting (PG, Pins 1–2)

For single-phase applications and for the primary device in multi-phase applications, the PG resistance (R_{PG} , also R6) is recommended to be about 100k Ω . The MPQ4371 has an open-drain PG output that indicates whether the regulator output is within its specific nominal output window. If using PG, connect it to a logic high level power source (e.g. 3.3V) via a pull-up resistor. PG goes high if V_{OUT} is within 94% to 106% of the nominal voltage; PG goes low if V_{OUT} exceeds 107% or falls below 93% of the nominal voltage. Float PG if it is not used.

For secondary devices in multi-phase applications, this pin can set the phase shift by connecting a resistor (R_{PHASE}) to ground. Table 2 shows the relationship between the phase shift and R_{PHASE} under high- and low-frequency conditions.

Phase Shift	R _{PHASE} at fsw_primary = 410kHz	R _{PHASE} at fsw_primary = 2.2MHz	
90°	33kΩ	4.87kΩ	
120º	46.4kΩ	7.32kΩ	
180°	73.2kΩ	12.1kΩ	
240°	97.6kΩ	16.9kΩ	
270°	115kΩ	19.1kΩ	
359°	150kΩ	26.1kΩ	

Table 2	2:	Phase	Shift	vs.	RPHASE
---------	----	-------	-------	-----	--------

Sync Input and MODE Selection (SYNCIN/MODE, Pin 3)

For single-phase applications and primary devices in multi-phase applications, when this pin is used as the sync input pin, f_{SW} can be synchronized to the rising edge of a clock signal applied at the SYNCIN/MODE pin. The recommended SYNCIN frequency range is between 90% and 110% of the set f_{SW} . When this pin is used for mode selection, pull this pin high so that the MPQ4371 operates in FCCM; pull this pin low or float this pin for AAM mode. Table 3 shows the detailed mode selection.

Table 3: N	Node	Selection
------------	------	-----------

SYNCIN/MODE Input	Operation
Floating	AAM mode
<0.4V	AAM mode
>1.4V	FCCM
External clock in	FCCM

For secondary devices in multi-phase applications, it is recommended to connect the SYNCIN/MODE pin of the secondary devices to the primary device's SYNCO pin. In this scenario, keep the primary device's SYNCO pin at a high impedance.

Enable and V_{IN} Under-Voltage Lockout (EN, Pin 4)

EN is a digital control pin that turns the regulator on and off.

Enabled by External Logic High/Low (H/L) Signal

When the EN voltage reaches about 0.7V, the VCC supply turns on. When V_{IN} exceeds about 2.7V, then V_{IN} provides an accurate reference voltage for the EN threshold. Forcing EN to exceed its rising threshold voltage of 1V turns on the device. The device is turned off by driving EN below 0.85V.

Configurable V_{IN} UVLO

When V_{IN} is sufficiently high, the chip can be enabled and disabled by the EN pin. The EN pin can generate a configurable V_{IN} UVLO threshold and hysteresis.

The MPQ4371 has an internal, fixed UVLO threshold. The rising threshold is 3.8V, while the falling threshold is about 2.9V. For applications that need a higher UVLO point, an external resistor divider can be placed between VIN and EN to achieve a higher equivalent UVLO threshold (see Figure 11).

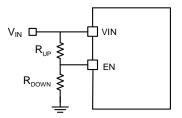


Figure 11: Adjustable UVLO Using EN Divider

The UVLO rising and falling thresholds can be calculated with Equation (1) and Equation (2), respectively:

$$VIN_{UV_RISING} = (1 + \frac{R_{UP}}{R_{DOWN}}) \times V_{EN_RISING}$$
(1)

$$VIN_{UV_FALLING} = (1 + \frac{R_{UP}}{R_{DOWN}}) \times V_{EN_FALLING}$$
(2)

Where $V_{EN_{RISING}}$ is 1V, and $V_{EN_{FALLING}}$ is 0.85V.

Selecting the Input Capacitors (VIN, Pins 5 and 14)

The step-down converters have a discontinuous input current, and require a capacitor to supply AC current to the converters while maintaining the DC input voltage. For the best performance, use low-ESR capacitors. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of their low ESR and small temperature coefficients.

For most applications, use a 4.7μ F to 10μ F capacitor. It is strongly recommended to use another, lower-value capacitor (e.g. 0.1μ F) with a small package size (0603) to absorb high-frequency switching noise. Place this capacitor as close to VIN and GND as possible.

Since C_{IN} absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated with Equation (3):

$$I_{CIN} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}})}$$
(3)

The worst-case condition occurs at $V_{IN} = 2 \times V_{OUT}$, calculated with Equation (4):

$$I_{CIN} = \frac{I_{LOAD}}{2}$$
(4)

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum, or ceramic. When using electrolytic or tantalum capacitors, add a small, high-quality ceramic capacitor (e.g. 0.1μ F) as close to the IC as possible. When using ceramic capacitors, ensure that they have enough capacitance to provide a sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple caused by the capacitance can be estimated with Equation (5):

$$\Delta V_{\rm IN} = \frac{I_{\rm LOAD}}{f_{\rm SW} \times C_{\rm IN}} \times \frac{V_{\rm OUT}}{V_{\rm IN}} \times (1 - \frac{V_{\rm OUT}}{V_{\rm IN}})$$
(5)

Selecting the Inductor and Output Capacitors (SW, Pins 9–10)

Selecting the Inductor

A 0.1μ H to 10μ H inductor with a DC current rating at least 25% higher than the maximum load current is recommended for most applications. For higher efficiency, choose an inductor with a lower DC resistance. A largervalue inductor results in less ripple current and a lower output voltage ripple, but also has a larger physical size, higher series resistance, and lower saturation current. A good rule to determine the inductance is to allow the inductor ripple current to be approximately 30% of the maximum load current. The inductance can be calculated with Equation (6):

$$L = \frac{V_{OUT}}{f_{sw} x \Delta I_L} x (1 - \frac{V_{OUT}}{V_{IN}})$$
(6)

Where ΔI_{L} is the peak-to-peak inductor ripple current.

Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum inductor peak current can be calculated with Equation (7):

$$I_{LP} = I_{LOAD} + \frac{V_{OUT}}{2xf_{sw}xL}x(1 - \frac{V_{OUT}}{V_{IN}})$$
(7)

Selecting the Output Capacitor

The output capacitor maintains the DC output voltage. Use ceramic, tantalum, or low-ESR electrolytic capacitors. For the best results, use low-ESR capacitors to keep the output voltage ripple low. The output voltage ripple can be estimated with Equation (8):

$$\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{SW}} \times L} \times (1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}) \times (R_{\text{ESR}} + \frac{1}{8f_{\text{SW}} \times C_{\text{OUT}}})$$
(8)

Where L is the inductance, and R_{ESR} is the output capacitor's equivalent series resistance (ESR).

For ceramic capacitors, the capacitance dominates the impedance at the switching frequency and causes the majority of the output voltage ripple. For simplification, the output voltage ripple can be calculated with Equation (9):

$$\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{8 \times f_{\text{SW}}^2 \times L \times C_{\text{OUT}}} \times (1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}) \quad (9)$$

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For tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output voltage ripple can be estimated with Equation (10):

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \times R_{ESR}$$
(10)

The characteristics of the output capacitor also affect the stability of the regulation system. The part can be optimized for a wide range of capacitance and ESR values.

Floating Driver and Bootstrap Charging (BST, Pin 15)

The BST capacitor (C_{BST} , also called C3) is recommended to be between $0.1\mu F$ to $0.47\mu F$.

It is not recommended to place a resistor (R_{BST}) in series with the BST capacitor, as this results in minimal EMI improvement and increases power dissipation. The MPQ4371 employs a sophisticated FET turn-on technique that greatly reduces the high-frequency EMI and eliminates the need for this resistor. If R_{BST} is necessary, it should be below 20 Ω .

The voltage between BST and SW (V_{BST-SW}) is regulated to about 5V by the dedicated internal bootstrap regulator. When V_{BOOT-SW} is below its regulation value, an N-channel MOSFET (NMOS) pass transistor connected from VCC to BST is turned on to charge C_{BST}. When the HS-FET is on, the BST voltage exceeds V_{CC}, which means that the bootstrap capacitor cannot be charged.

Under conditions with higher duty cycles, the time available for bootstrap charging is shorter, so the bootstrap capacitor may not be charged sufficiently. External circuitry can be used to ensure that the bootstrap voltage remains in the normal operation region.

If the bootstrap voltage reaches its under-voltage lockout (UVLO) threshold, the HS-FET turns off, and the LS-FET turns on with a minimum off time to refresh the bootstrap voltage with the set fsw.

The BST refresh function can only be triggered during the start-up period, sleep mode, or if the feedback over-voltage (OV) condition is triggered.

Sync Output (SYNCO, Pin 16)

For single-phase applications and for the primary device in multi-phase applications, the SYNCO

pin outputs a clock signal in phase with the internal oscillator signal or external SYNCIN clock.

For secondary devices in multi-phase applications, this pin can be connected to the SYNCIN/MODE pin of the primary device, or it can be pulled low or high to select AAM mode or FCCM, respectively. The mode setting threshold is same as the selections for the SYNCIN/MODE pin (see Table 3 on page 70).

Current Sharing (ICS, Pins 17–18)

The ICS pin's function is disabled if the voltage of this pin exceeds 2.4V. Connect ICS to VCC to disable this function in single-phase applications.

In multi-phase applications, connect the ICS pins together for each MPQ4371 phase. Connect a small capacitor between the ICS pin and GND to filter the noise disturbance. For high-frequency conditions (e.g. 2.2MHz), it is recommended for the capacitance to be between 22pF and 180pF. For low-frequency conditions (e.g. 410kHz), it is recommended for the capacitance to be between 100pF and 1.2nF.

Internal LDO Supply (VBIAS, Pin 19)

The VBIAS capacitor (C5) is recommended to be 1μ F.

The VBIAS pin is the internal LDO's supply pin. When the VBIAS pin is connected to a 5V voltage, VBIAS is the power supply for the VCC regulator. The input supply current can be lower to obtain a higher efficiency. When V_{BIAS} exceeds 4.5V, this pin takes over VCC; when V_{BIAS} is below 4.3V, this function is disabled.

VBIAS can be connected directly to the output voltage when V_{OUT} is between 4.6V to 5.5V to improve the converter's efficiency, especially at high frequencies. Alternatively, connect VBIAS to another 5V rail if one is available in the system, and the current draw is <30mA. Add one decoupling capacitor between the VBIAS pin and GND if this function is used.

When there is no suitable power source for VBIAS, or its function is not used, connect this pin to VOUT or GND. For applications where $V_{OUT} > 5.5V$, avoid connecting the VBIAS pin to the output. Do not provide an external VBIAS voltage before VIN. Do not float this pin.



Internal LDO Supply (VCC, Pin 20)

The VCC capacitor (C6) is recommended to be $1\mu\text{F}.$

The VCC capacitor should be 10 times larger than BST capacitor. A VCC capacitor larger than 68μ F is not recommended.

The internal circuitry is powered by the internal 5V VCC regulator. This regulator uses VIN as its input and operates across the full V_{IN} range. When V_{IN} exceeds 5V, V_{CC} is in full regulation and maintains a 5V voltage. When V_{IN} is lower, the VCC output degrades.

When VCC is powered by VBIAS, V_{CC} follows $V_{\text{BIAS}}.$

Setting the Feedback (VOUT/FB, Pin 22)

For the adjustable output version, V_{FB} is typically 0.6V. The external resistor divider connected to FB sets the output voltage (see Figure 12).

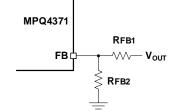


Figure 12: Feedback Divider Network of Adjustable-Output Version

Calculate R_{FB2} with Equation (11):

$$R_{FB2} = \frac{R_{FB1}}{\frac{V_{OUT}}{0.6V} - 1}$$
(11)

Table 4 lists the recommended feedback resistor values for common output voltages.

 Table 4: Feedback Resistor Selection for

 Adjustable Output Version

-	-	
V оит (V)	R _{FB1} (kΩ)	R _{FB2} (kΩ)
1.0	66.5 (1%)	100 (1%)
3.3	100 (1%)	22.1 (1%)
5.0	100 (1%)	13.7 (1%)

For the fixed output version, the FB resistor divider is integrated internally, so connect FB to V_{OUT} directly to set the output voltage (see Figure 13). The following fixed outputs are available: 1V, 1.2V, 1.8V, 2.5V, 3.3V, 3.8V, and 5V.

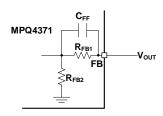


Figure 13: Feedback Divider Network of Fixed-Output Version

Table 5 shows the relationship between the internal R_{FB} and $V_{\text{OUT}}.$

Vоит (V)	Vout (V) R _{FB2} (MΩ)		Сғғ (рҒ)
1.0	2.0	1.333	3.0
1.2	2.0	2.0	3.0
1.8	2.0	4.0	3.0
2.5	2.0	6.333	3.0
3.3	2.0	9.0	3.0
3.8	2.0	10.667	3.0
5.0	2.0	14.667	3.0

Setting the Switching Frequency Setting (f_{sw}) (FREQ, Pin 23)

A resistor (R3, also called R_{FREQ}) can be used to $f_{\text{SW}}.$ Table 6 shows the R_{FREQ} values to set the adjustable $f_{\text{SW}}.$

Table 6: RFREQ vs. fsw				
R _{FREQ} (kΩ) f _{sw} (kHz)				
13	2500			
14.3	2330			
15	2200			
15.8	2100			
18.7	1800			
22.6	1520			
27.4	1270			
32.4	1100			
41.2	870			
51.1	710			
71.5	520			
88.7	410			
100	370			
130	285			
191 200				

GND Connection (PGND, Pins 7–8 and Pins 11–12; AGND, Pin 21)

See the PCB Layout Guidelines section on page 74 for more details.



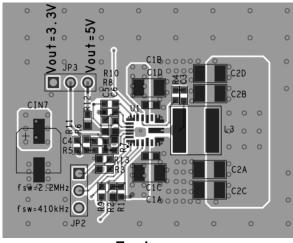
PCB Layout Guidelines (14)

Efficient PCB layout, especially for input capacitor placement, is critical for stable operation. A 4-layer layout is strongly recommended to improve thermal performance. For the best results, refer to Figure 14 and follow the guidelines below:

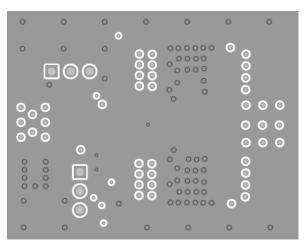
- 1. Place symmetrical input capacitors as close to VIN and GND as possible.
- 2. Use a large ground plane to connect directly to PGND.
- 3. Add vias near PGND if the bottom layer is a ground plane.
- 4. Ensure that the high-current paths at GND and VIN have short, direct, and wide traces.
- 5. Place the ceramic input capacitor, especially the small package size (0603) input bypass capacitor, as close to VIN and PGND as possible to minimize high-frequency noise
- 6. Keep the connection between the input capacitor and VIN as short and wide as possible.
- 7. Place the VCC capacitor as close to VCC and GND as possible.
- 8. Route SW and BST away from sensitive analog areas, such as FB.
- 9. Use multiple vias to connect the power planes to the internal layers.

Note:

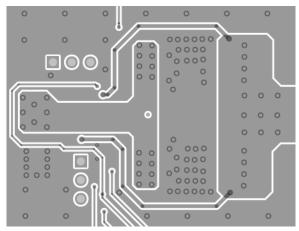
15) The recommended PCB layout is based on Figure 15 on page 75.



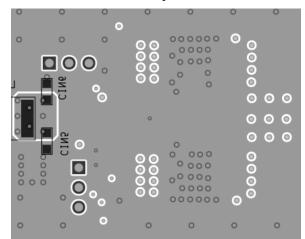
Top Layer



Mid-Layer 1



Mid-Layer 2



Bottom Layer Figure 14: Recommended PCB Layout



TYPICAL APPLICATION CIRCUITS

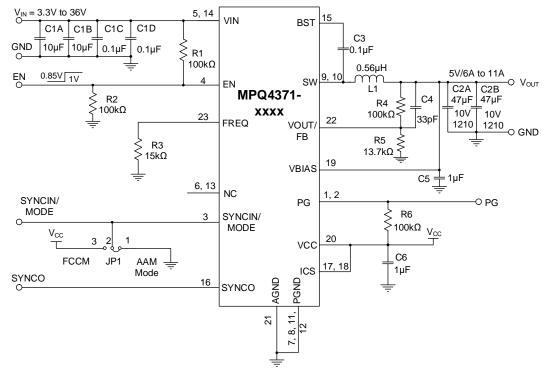


Figure 15: Typical Application Circuit (Single-Phase, Vout Adjustable for the MPQ4371-xxxx, Vout = 5V, fsw = 2.2MHz)

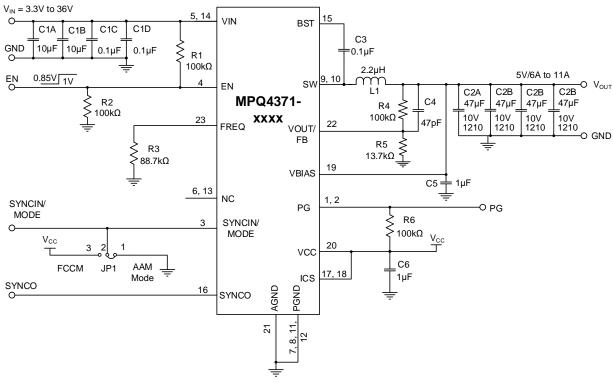


Figure 16: Typical Application Circuit (Single-Phase, Vout Adjustable for the MPQ4371-xxxx, Vout = 5V, fsw = 410kHz)



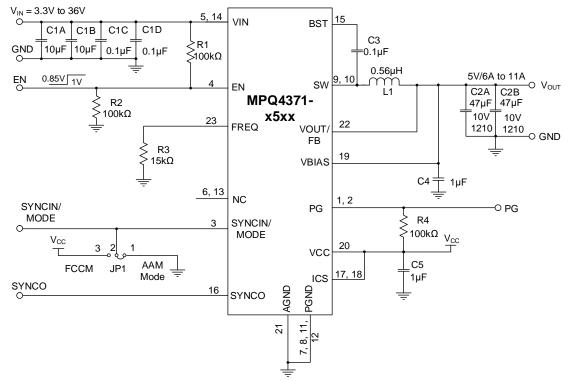


Figure 17: Typical Application Circuit (Single-Phase, 5V Fixed Vout for the MPQ4371-xxxx, fsw = 2.2MHz)

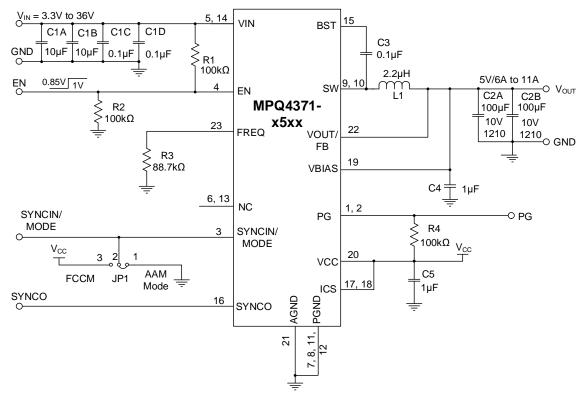


Figure 18: Typical Application Circuit (Single-Phase, 5V Fixed Vout for the MPQ4371-xxxx, fsw = 410kHz)



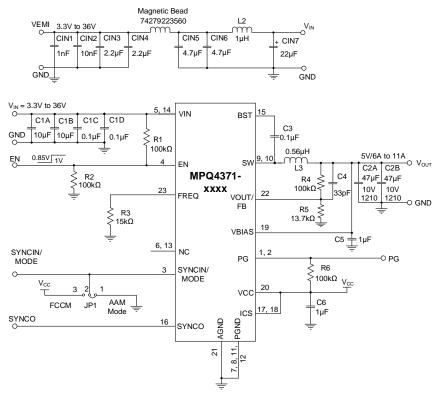
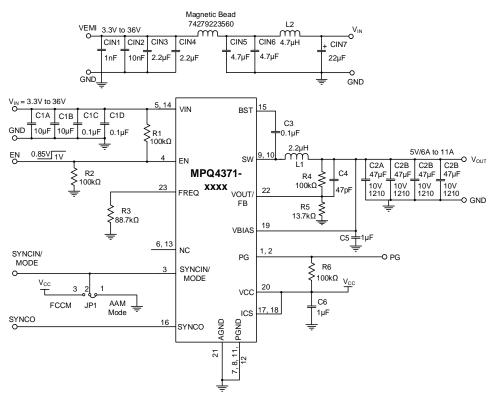
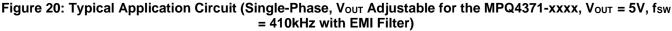


Figure 19: Typical Application Circuit (Single-Phase, Vout Adjustable for the MPQ4371-xxxx, Vout = 5V, fsw = 2.2MHz with EMI Filter)







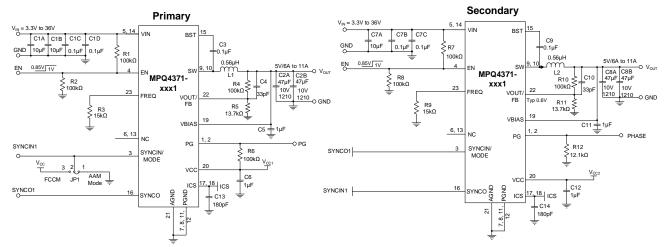


Figure 21: Typical Application Circuit (Dual-Phase, V_{OUT} Adjustable for the MPQ4371-xxx1, V_{OUT} = 5V, f_{SW} = 2.2MHz)

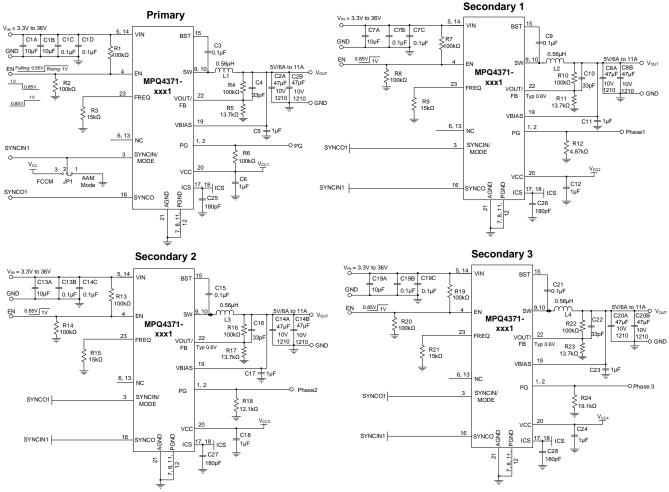


Figure 22: Typical Application Circuit (Four-Phase, Vout = 5V for the MPQ4371-xxx1, fsw = 2.2MHz)



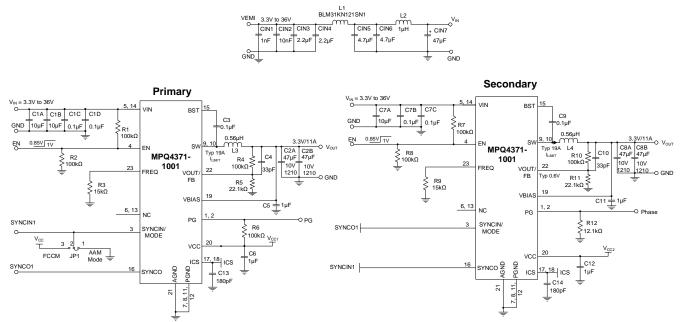
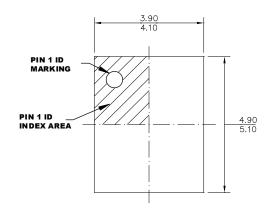


Figure 23: Typical Application Circuit (Dual-Phase, V_{OUT} Adjustable for the MPQ4371-1001, V_{OUT} = 3.3V, f_{SW} = 2.2MHz, I_{OUT} = 22A with EMI Filter)

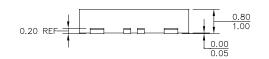


PACKAGE INFORMATION

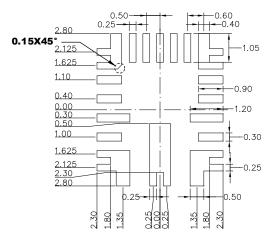
QFN-23 (4mmx5mm)



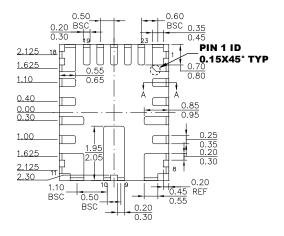
TOP VIEW



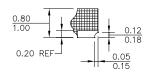
SIDE VIEW



RECOMMENDED LAND PATTERN



BOTTOM VIEW



SECTION A-A

NOTE:

1) THE LEAD SIDE IS WETTABLE.

2) ALL DIMENSIONS ARE IN MILLIMETERS.

3) LEAD COPLANARITY SHALL BE 0.08 MILLIMETERS MAX.

- 4) JEDEC REFERENCE IS MO-220.
- 5) DRAWING IS NOT TO SCALE.



0.50

.55 65

0.50 BSC

2.125

<u>1.625</u>

<u>1.10</u> 0.40

0.00 0.30

1.00 1.625 2.125 2.30

1.10 BSC 0.60

BSC 0

| 0

0.85

0.20 0.45 0.55

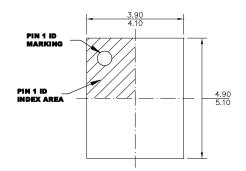
0.80

PIN 1 ID

0.15X45° TYP

PACKAGE INFORMATION (continued)

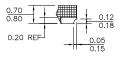
TQFN-23 (4mmx5mm)



TOP VIEW



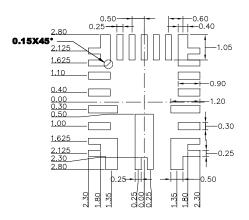
SIDE VIEW



BOTTOM VIEW

0.20





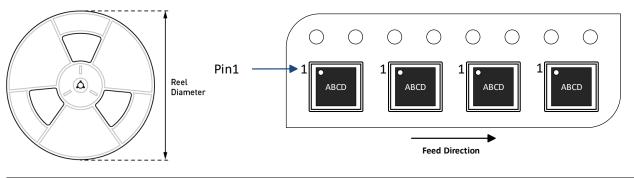
RECOMMENDED LAND PATTERN

NOTE:

- 1) THE LEAD SIDE IS WETTABLE.
- 2) ALL DIMENSIONS ARE IN MILLIMETERS.
- 3) LEAD COPLANARITY SHALL BE 0.08
- MILLIMETERS MAX.
- 4) JEDEC REFERENCE IS MO-220.
- 5) DRAWING IS NOT TO SCALE.



CARRIER INFORMATION



Part Number	Package Description	Quantity/ Reel	Quantity/ Tube ⁽¹⁶⁾	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch
MPQ4371GVE-xxxx- AEC1-Z	QFN-23 (4mmx5mm)	5000	N/A	13in	12mm	8mm
MPQ4371GVTE-xxxx- AEC1-Z	TQFN-23 (4mmx5mm)	5000	N/A	13in	12mm	8mm

Note:

16) N/A indicates "not available" in tubes. For the 500-piece tape & reel prototype quantities, contact the factory. (The ordering code for a 500-piece partial reel is "-P"; the tape & reel dimensions are the same as the full reel.)



REVISION HISTORY

Revision #	Revision Date	Description	Pages Updated
1.0	3/21/2024	Initial Release	-

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